

## General Description

The MAX14720/MAX14750 are compact power-management solutions for space-constrained, battery-powered applications where size and efficiency are critical. Both devices integrate a power switch, a linear regulator, a buck regulator, and a buck-boost regulator.

The MAX14720 is designed to be the primary power-management device and is ideal for either non-rechargeable battery (coin-cell, dual alkaline) applications or for rechargeable solutions where the battery is removable and charged separately. The device includes a button monitor and sequencer.

The MAX14750 works well as a companion to a charger or PMIC in rechargeable applications. It provides direct pin control of each function and allows greater flexibility for controlling sequencing.

The devices include two programmable micro-I<sub>Q</sub>, high-efficiency switching converters: a buck-boost regulator and a synchronous buck regulator. These regulators feature a burst mode for increased efficiency during light-load operation.

The low-dropout linear regulator has a programmable output. It can also operate as a power switch that can disconnect the quiescent load of system peripherals.

The devices also include a power switch with battery-monitoring capability. The switch can isolate the battery from all system loads to maximize battery life when not operating. It is also used to isolate the battery-impedance measurements. This switch can operate as a general-purpose load switch as well.

The MAX14720 includes a programmable power controller that allows the device to be configured either for use in applications that require a true off state or for always-on applications. This controller provides a delayed reset signal, voltage sequencing, and customized button timing for on/off control and recovery hard reset.

Both devices also include a multiplexer for monitoring the power inputs and outputs of each function.

These devices are available in a 25-bump, 0.4mm pitch, 2.26mm x 2.14mm wafer-level package (WLP) and operate over the -40°C to +85°C extended temperature range.

## Benefits and Features

- Extended System Battery Use Time
  - Micro-I<sub>Q</sub> 250mW Buck-Boost Regulator
    - Input Voltage from 1.8V to 5.5V
    - Output Voltage Programmable from 2.5V to 5V
    - 1.1µA Quiescent Current
    - Programmable Current Limit
  - Micro-I<sub>Q</sub> 200mA Buck Regulator
    - Input Voltage from 1.8V to 5.5V
    - Output Voltage Programmable from 1.0V to 2.0V
    - 0.9µA Quiescent Current
  - Micro-I<sub>Q</sub> 100mA LDO
    - Input Voltage From 1.71V to 5.5V
    - Output Programmable From 0.9V to 4.0V
    - 0.9µA Quiescent Current
    - Configurable as Load Switch
- Extend Product Shelf-Life
  - Battery Seal Mode (MAX14720)
    - 120nA Battery Current
  - Power Switch On-Resistance
    - 250mΩ (max) at 2.7V
    - 500mΩ (max) at 1.8V
  - Battery Impedance Detector
- Easy-to-Implement System Control
  - Configurable Power Mode and Reset Behavior (MAX14720)
    - Push-Button Monitoring to Enable Ultra-Low Power Shipping Mode
    - Disconnects All Loads From Battery and Reduces Leakage to Less than 1µA
    - Power-On Reset (POR) Delay and Voltage Sequencing
  - Individual Enable Pins (MAX14750)
  - Voltage Monitor Multiplexer
  - I<sup>2</sup>C Control Interface

## Applications

- Wearable Medical Devices
- Wearable Fitness Devices
- Portable Medical Devices

**Ordering Information** appears at end of data sheet.

### Absolute Maximum Ratings

(Voltages Referenced to GND.)

BIN, LIN, SDA, SCL, SWIN, BEN, SWOUT, SWEN,  
 LEN, HVEN, HVIN, HVOUT, MON, CAP, V<sub>CC</sub>,  
 MPC, KIN, RST, KOUT ..... -0.3V to +6.0V  
 HVILX ..... -0.3V to V<sub>HVIN</sub> + 0.3V  
 HVOLX ..... -0.3V to V<sub>HVOUT</sub> + 0.3V  
 BLX, BOUT ..... -0.3V to (V<sub>BIN</sub> + 0.3V)  
 LOUT ..... -0.3V to (V<sub>LIN</sub> + 0.3V)  
 GND ..... -0.3V to +0.3V

Continuous-Current into HVIN, BIN, SWIN ..... ±1000mA  
 Continuous-Current into Any Other Terminal ..... ±100mA  
 Continuous Power Dissipation (multilayer board at +70°C):  
 5x5 Array 25-Ball 2.26mm x 2.14mm 0.4mm Pitch WLP  
 (derate 19.07mW/°C) ..... 1.525W  
 Operating Temperature Range ..... -40°C to +85°C  
 Junction Temperature ..... +150°C  
 Storage Temperature Range ..... -65°C to +150°C  
 Lead Temperature (soldering 10s) ..... +300°C  
 Soldering Temperature (reflow) ..... +260°C

### Package Thermal Characteristics (Note 1)

WLP

Junction-to-Ambient Thermal Resistance (θ<sub>JA</sub>) ..... 52.43°C/W

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maximintegrated.com/thermal-tutorial](http://www.maximintegrated.com/thermal-tutorial).

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

### Electrical Characteristics

(V<sub>CC</sub> = V<sub>BIN</sub> = V<sub>LIN</sub> = V<sub>HVIN</sub> = V<sub>SWIN</sub> = 2.7V, T<sub>A</sub> = -40°C to +85°C, all registers in their default state, unless otherwise noted. Typical values are at T<sub>A</sub> = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>SUPPLY CURRENT</b>						
Seal Input Current	I <sub>SEAL</sub>	Seal mode, all functions disabled		0.12	1	µA
Off Input Current	I <sub>OFF</sub>	No blocks enabled, no battery measurement active		1.2	2.8	µA
MON Input Current	I <sub>MON</sub>	No blocks enabled, no battery measurement active, MON enabled, MONCtr[2:0] = 000.		4	7.2	µA
Switch Input Current	I <sub>SW</sub>	Switch enabled, I <sub>SWOUT</sub> = 0A		1.2	2.8	µA
LDO Input Current	I <sub>LDO</sub>	LDO enabled, I <sub>LOUT</sub> = 0A		2.1	4.4	µA
		LDO enabled, LIN UVLO enabled, I <sub>LOUT</sub> = 0A		2.4	4.8	
		LDO enabled, switch mode, I <sub>LOUT</sub> = 0A		1.5	3.2	
Buck Input Current	I <sub>BUCK</sub>	Buck enabled, I <sub>BOUT</sub> = 0A		2	4.1	µA
		Buck enabled, BIN UVLO enabled, I <sub>BOUT</sub> = 0A		2.2	4.5	
Buck-Boost Input Current	I <sub>BCKBST</sub>	Buck-Boost enabled, I <sub>HVOUT</sub> = 0A, V <sub>HVOUT</sub> = 4V		2	4.7	µA
		Buck-Boost enabled, BIN UVLO enabled, I <sub>HVOUT</sub> = 0A, V <sub>HVOUT</sub> = 4V		2.3	5	

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
On Input Current	$I_{ON}$	LDO, buck, and buck-boost enabled; BIN UVLO and LIN UVLO enabled; $I_{SWOUT} = I_{LOUT} = I_{BOUT} = I_{HVOUT} = 0A$		4.4	8.3	$\mu A$
<b>POWER SEQUENCE</b>						
Boot Time	$t_{BOOT}$	MAX14720	9.9	11	12.1	ms
		MAX14750	21.6	24	26.4	ms
Reset Time	$t_{RST}$	MAX14720	72	80	88	ms
<b>POWER SWITCH</b>						
Input Voltage Range	$V_{SWIN}$	$V_{SWIN} \leq V_{CC}$	1.8		5.5	V
Quiescent Supply Current	$I_{Q\_SW}$	$I_{SWOUT} = 0A$		0.05	0.09	$\mu A$
Switch On-Resistance	$R_{ON\_SW}$	$I_{SWOUT} = 200mA$		0.16	0.25	$\Omega$
		$V_{SWIN} = 1.8V$ , $I_{SWOUT} = 200mA$		0.27	0.5	
Maximum Output Current	$I_{SWOUT\_MAX}$		200			mA
Turn-On Time	$t_{ON\_SW}$	$I_{SWOUT} = 0mA$ , $C_{SWOUT} = 100\mu F$ , time from 10% to 90% of $V_{SWIN}$ , $SWSOftStart = 0$		0.65		ms
		$I_{SWOUT} = 0mA$ , $C_{SWOUT} = 100\mu F$ , time from 10% to 90% of $V_{SWIN}$ , $SWSOftStart = 1$		13.8		ms
Short-Circuit Current Limit	$I_{SHRT\_SW}$	$V_{SWOUT} = GND$ , $SWSOftStart = 0$	200	460	700	mA
Soft-Start Current Limit	$I_{SSTR\_SW}$	$V_{SWOUT} = GND$ , $SWSOftStart = 1$	9	25	54	mA
Thermal-Shutdown Threshold	$T_{SHDN\_SW}$	$T_J$ rising		150		$^{\circ}C$
Thermal-Shutdown Hysteresis	$T_{SHDN\_HYST\_SW}$			20		$^{\circ}C$
<b>BUCK BOOST CONVERTER (<math>C_{OUT} = 10MF</math>, <math>L = 4.7MF</math>, unless otherwise noted.)</b>						
Input Voltage Range	$V_{HVIN}$		1.8		5.5	V
Quiescent Supply Current	$I_{Q\_BOOST}$	$V_{HVOUT} = 4V$ , $I_{HVOUT} = 0A$ , BIN UVLO disabled		1.1	2.6	$\mu A$
		$V_{HVOUT} = 4V$ , $I_{HVOUT} = 0A$ , BIN UVLO enabled		1.3	3	$\mu A$
Minimum Input Voltage Startup	$V_{HVIN\_STUP}$	$I_{LOAD} = 1mA$ , minimum input voltage for correct startup of the buck-boost	1.9			V

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^\circ C$  to  $+85^\circ C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^\circ C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Maximum Output Operating Power	$P_{MAXHVOUT}$	$V_{HVIN} = 3V$	250			mW
Output Voltage	$V_{HVOUT}$	100mV step	2.5		5	V
Output Accuracy	$ACC_{HVOUT}$	$I_{HVOUT} = 1mA$ , average output $C_{OUT} \geq 10\mu F$	-3		+3	%
Line Regulation Error	$V_{HVINREG\_BOOST}$	$V_{HVIN} = 1.8V$ to $5.5V$ , $I_{HVOUT} = 10\mu A$ , $V_{HVOUT} = 4V$ , $I_{SET} = 100mA$	-1	0.1	+1	%/V
Load Regulation Error	$V_{LOADREG\_BOOST}$	$V_{HVOUT} = 4V$ , $I_{HVOUT} = 10\mu A$ to $50mA$ , $I_{SET} = 100mA$		100		mV/A
		$V_{HVOUT} = 4V$ , $I_{HVOUT} = 10\mu A$ to $100mA$ , $I_{SET} = 100mA$		310		mV/A
Line Transient	$V_{LINETRAN\_BST}$	$V_{HVOUT} = 4V$ , $I_{SET} = 100mA$ , $V_{HVIN} = V_{CC} = 2.5V$ to $5V$ , $0.2\mu s$ rise time		15		mV
Load Transient	$V_{LOADTRAN\_BST}$	$I_{HVOUT} = 0mA$ to $10mA$ , 200ns rise time, $V_{HVOUT} = 4V$ , $I_{SET} = 100mA$		9		mV
		$I_{HVOUT} = 0mA$ to $100mA$ , 200ns rise time, $V_{HVOUT} = 4V$ , $I_{SET} = 100mA$		31		mV
Oscillator Frequency	$f_{OSC\_BST}$		1.78	2	2.25	MHz
Passive Discharge Pulldown Resistance	$R_{PDL\_BST}$		5	10	16	k $\Omega$
Active Discharge Current	$I_{ACTDL\_BST}$	$V_{HVIN} = 3V$	6	19	38	mA
Turn-On Time	$t_{ON\_BOOST}$	Time from enable to full current capability		100		ms
UVLO on HVOUT	$V_{HVOUT\_UVLO}$	UVLO voltage on HVOUT rising	1.6	1.75	1.9	V
UVLO Threshold Hysteresis	$V_{UVLO\_HYS}$			150		mV
Precharge Current	$I_{PC\_BOOST}$	Precharge current. $V_{HVIN} = 1.8V$ , $V_{HVOUT} = 1.65V$	4	6.5	9	mA
Startup Input Current	$I_{INSTUP\_BST}$	Input startup current. $V_{HVIN} = 1.8V$ , $V_{HVOUT} = 1.6V$		11		mA
Startup Output Current	$I_{OSTUP\_BST}$	Output startup current. $V_{HVIN} = 1.8V$ , $V_{HVOUT} = 5V$		6.5		mA
Pulse Mode Input Current Limit	$I_{PLS\_IN}$	$V_{HVOUT} = 4V$ , $V_{HVIN} < V_{HVOUT} -$ $0.5V$ , $f_{SW} = f_{OSC}/10$ , $I_{SET} = 100mA$		6.6		mA

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Pulse Mode Switching Period Ratio	$T_{RATIO}$	$f_{OSC}/f_{SW}$ , 128 steps	10		138	
Short-Circuit Peak Current Limit	$I_{SHRT\_BOOST}$	$V_{HVOUT} = GND$ .	0.4	1.1	1.9	A
Thermal-Shutdown Threshold	$T_{SHDN\_BST}$	$T_J$ rising		150		$^{\circ}C$
Thermal-Shutdown Hysteresis	$T_{SHDN\_HYST\_BST}$			21		$^{\circ}C$
<b>BUCK CONVERTER (<math>C_{OUT} = 10MF</math>, <math>L = 2.2MH</math>, unless otherwise noted.)</b>						
Input Voltage Range	$V_{BIN}$		1.8		5.5	V
Quiescent Supply Current	$I_{Q\_BUCK}$	$I_{BOUT} = 0A$		0.8	1.6	$\mu A$
		$I_{BOUT} = 0A$ , BIN UVLO enabled		1	2	
		$I_{BOUT} = 0A$ , BuckMd[1:0] = 01			4.8	mA
Maximum Operative Output Current	$I_{MAXBOUT}$		250			mA
Output Voltage	$V_{BOUT}$	25mV step	1		2	V
Output Accuracy	$A_{CC\_BOUT}$	$V_{BIN} = (V_{BOUT} + 0.1V)$ or higher, $I_{BOUT} = 1mA$ ; average output	-3		+3	%
Dropout Voltage	$V_{DROP\_BUCK}$	$I_{BOUT} = 0A$		95	120	mV
Line Regulation Error	$V_{LINEREG\_BUCK}$	$V_{BIN} =$ from 2V to 5V, $V_{BOUT} = 1.2V$		0.65		%/V
Load Regulation Error	$V_{LOADREG\_BUCK}$	BuckInteg = 1, $I_{BOUT} = 200mA$		23		mV
Line Transient	$V_{LINETRAN\_BUCK}$	$V_{BOUT} = 1.2V$ , $V_{BIN} = V_{CC}$ : 2.0V to 5V, 1 $\mu s$ rise time		50		mV
Load Transient	$V_{LOADTRAN\_BUCK}$	$I_{BOUT} = 0mA$ to 200mA, 200ns rise time		70		mV
Oscillator Frequency	$f_{OSC\_BK}$		1.78	2	2.25	MHz
Passive Discharge Pull-Down Resistance	$R_{PDL\_BK}$		5	10	16	k $\Omega$
Active Discharge Current	$I_{ACTDL\_BK}$		5.5	17	33	mA
Turn-On Time	$t_{ON\_BUCK}$	Time from enable to full current capability; BuckFst = 0		60		ms
		Time from enable to full current capability; BuckFst = 1		30		ms
Startup Output Current	$I_{STUP\_BK}$	BuckFst = 0		18		mA

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Startup Output Current	$I_{STUP\_BK}$	BuckFst = 1		42		mA
Short-Circuit Peak Current Limit	$I_{SHRT\_BUCK}$	$V_{BOUT} = GND$ .	0.54	0.8	2.19	A
Thermal-Shutdown Threshold	$T_{SHDN\_BUCK}$	$T_J$ rising		150		$^{\circ}C$
Thermal-Shutdown Hysteresis	$T_{SHDN\_HYST\_BUCK}$			21		$^{\circ}C$
<b>LDO (<math>C_{LDO} = 1\mu F</math>, unless otherwise noted. Typical values are with <math>I_{LDO} = 10mA</math>, <math>V_{LDO} = 2V</math>)</b>						
Input Voltage Range	$V_{LIN}$	LDO mode	1.71		5.5	V
		Switch mode	1.2		5.5	
Quiescent Supply Current	$I_{Q\_LDO}$	$I_{LDO} = 0A$		0.9	1.9	$\mu A$
		$I_{LDO} = 0A$ , LIN UVLO enabled		1.1	2.2	
		$I_{LDO} = 0A$ , switch mode		0.3	0.5	
Quiescent Supply Current in dropout	$I_{Q\_LDO\_DRP}$	$I_{LDO} = 0A$ , $V_{SET} = 2.8V$		2.1	4.6	$\mu A$
Maximum Output Current	$I_{LDO\_MAX}$	$V_{LIN} > 1.8V$	100			mA
		$V_{LIN} = 1.8V$ or lower	50			mA
Output Voltage	$V_{LDO}$	100mV step	0.9		4	V
Output Accuracy	$ACC_{LDO}$	$V_{LIN} = (V_{LDO} + 0.5V)$ or higher, $I_{LDO} = 1mA$	-3.1		+3.1	%
Dropout Voltage	$V_{DROP\_LDO}$	$V_{LIN} = V_{SET} = 2.7V$ , $I_{LDO} = 100mA$			100	mV
Line Regulation Error	$V_{LINEREG\_LDO}$	$V_{LIN} = (V_{LDO} + 0.5V)$ to 5.5V	-0.5		+0.5	%/V
Load Regulation Error	$V_{LOADREG\_LDO}$	$V_{LIN} = 1.8V$ or higher, $I_{LDO} = 100\mu A$ to 100mA		0.001	0.005	%/mA
Line Transient	$V_{LINETRAN\_LDO}$	$V_{LIN} = 4V$ to 5V, 200ns rise time		$\pm 35$		mV
		$V_{LIN} = 4V$ to 5V, 1 $\mu s$ rise time		$\pm 25$		mV
Load Transient	$V_{LOADTRAN\_LDO}$	$I_{LDO} = 0mA$ to 10mA, 200ns rise time		100		mV
		$I_{LDO} = 0mA$ to 100mA, 200ns rise time		200		mV
Passive Discharge Pulldown Resistance	$R_{PDL\_LDO}$		4	10	18	k $\Omega$
Active Discharge Current	$I_{ACTDL\_LDO}$		5	20	40	mA

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Switch Mode Resistance	$R_{ON\_LDO}$	$V_{LIN} = 1.8V$ , $I_{LOUT} = 50mA$			1	$\Omega$
		$V_{LIN} = 1.2V$ , $I_{LOUT} = 5mA$			3	
Turn-On Time	$t_{ON\_LDO}$	$I_{LOUT} = 0mA$ , time from 10% to 90% of final regulation value		0.95		ms
		$I_{LOUT} = 0mA$ , time from 10% to 90% of $V_{LIN}$ , Switch mode		1.8		ms
Short-Circuit Current Limit	$I_{SHRT\_LDO}$	$V_{LOUT} = GND$		380		mA
		$V_{LOUT} = GND$ , Switch mode		370		mA
Thermal-Shutdown Threshold	$t_{SHDN\_LDO}$	$T_J$ rising		150		$^{\circ}C$
Thermal-Shutdown Hysteresis	$t_{SHDN\_HYST\_LDO}$			21		$^{\circ}C$
Output Noise	$OUT_{NOISE\_LDO}$	10Hz to 100kHz, $V_{LIN} = 5V$ , $V_{LOUT} = 3.3V$		150		$\mu V_{RMS}$
		10Hz to 100kHz, $V_{LIN} = 5V$ , $V_{LOUT} = 2.5V$		125		
		10Hz to 100kHz, $V_{LIN} = 5V$ , $V_{LOUT} = 1.2V$		90		
		10Hz to 100kHz, $V_{LIN} = 5V$ , $V_{LOUT} = 0.9V$		80		
<b>BATTERY IMPEDANCE MEASUREMENT</b>						
SWOUT Allowed Supply Range	$V_{SWOUT}$		2		5.5	V
SWOUT UVLO	$U_{VLOSWOUT}$	Falling edge	1.92		2	V
SWOUT UVLO Hysteresis	$U_{VLOHYST}$	Hysteresis		30		mV
$V_{CC}$ Impedance Test Current Range	$I_{BIM\_CUR}$	Programmable current source with step change of 2x	250		8000	$\mu A$
$V_{CC}$ Impedance Test Current Accuracy	$I_{BIM\_ACC}$	$V_{CC} > 1.2V$	-10		10	%
$V_{CC}$ Input Divider Resistance	$R_{VCC}$	$V_{CC}$ measure enabled		1.5		$M\Omega$
Measurable $V_{CC}$ Voltage Range	$V_{CC\_FS}$	Allowed $V_{CC}$ voltages range for SAR ADC operation	1.2		3.6	V
$V_{CC}$ Voltage Resolution LSB	$V_{CC\_LSB}$			10.2		mV

### Electrical Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , all registers in their default state, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Worst-Case Accuracy of Single $V_{CC}$ Measurement	$V_{CC\_ACC}$	$V_{CC} = 1.2V$	-72		+72	mV
		$V_{CC} = 3.6V$	-100		+100	
Worst-Case Accuracy Of Differential $V_{CC}$ Measurement	$V_{CC\_ACC\_DIFF}$	$V_{CC1} - V_{CC2} = 100mV$	-22		+22	%
		$V_{CC1} - V_{CC2} = 1.0V$	-3.5		+3.5	
$V_{CC}$ Voltage Wait Time Accuracy	$t_{WAIT\_ACC}$	10ms, 100ms, 1s programmable $t_{WAIT}$	-10		+10	%
SAR ADC $V_{CC}$ Voltage Conversion Time	$t_{CONV}$	Actual full $V_{CC}$ measurement time is $t_{WAIT} + t_{CONV}$		120		$\mu s$
<b>MONITOR MULTIPLEXER</b>						
SWIN To MON Switch Resistance	$R_{MON\_SWIN}$	$V_{SWIN} > 1.8V$ , $I_{LOAD} = 2mA$		80	120	$\Omega$
SWOUT/BIN/HVIN/HVOUT/LIN To MON Switch Resistance	$R_{MON\_HV}$	Sensed pin voltage $> 1.8V$ , $I_{LOAD} = 500\mu A$			400	$\Omega$
LOUT/BOU To MON Switch Resistance	$R_{MON\_LV}$	Sensed pin voltage $> 0.9V$ , $I_{LOAD} = 500\mu A$			500	$\Omega$
BBM Time	$t_{BBM}$	Anytime $MONCtr[2:0]$ changed		80		$\mu s$
Pulldown Resistance	$R_{MON\_PD}$	$MONHiZ = 0$		100		$k\Omega$
<b>UVLO/POR</b>						
Input Voltage Range	$V_{VCC}$		1.8		5.5	V
BIN UVLO Threshold Rising	$V_{TH\_BIN\_RISE}$		1.68	1.73	1.77	V
BIN UVLO Threshold Falling	$V_{TH\_BIN\_FALLING}$		1.66	1.71	1.75	V
LIN UVLO Threshold Rising	$V_{TH\_LIN\_RISE}$		1.64	1.68	1.72	V
LIN UVLO Threshold Falling	$V_{TH\_LIN\_FALLING}$		1.62	1.66	1.7	V
POR Falling	$V_{TH\_POR\_FALLING}$	Seal mode	0.76	1.21		V
		No seal mode	1.55	1.66	1.77	V
POR Rising	$V_{TH\_POR\_RISING}$	Seal mode		1.27	1.71	V
		No seal mode	1.58	1.69	1.8	V



## Electrical Characteristics (continued)

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PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>DIGITAL SIGNALS (<math>V_{CC} = 1.8V</math> to <math>5.5V</math>, unless otherwise noted. Typical values are at <math>V_{CC} = 2.7V</math>.)</b>						
Input Logic-High (SDA, SCL, SWEN, $\overline{KIN}$ , BEN, MPC, LEN, HVEN)	$V_{IH}$	No seal mode	1.4			V
Input Logic-Low (SDA, SCL, SWEN, $\overline{KIN}$ , BEN, MP, LEN, HVEN)	$V_{IL}$	No seal mode			0.45	V
		No seal mode, $V_{CC} \geq 2.7V$			0.5	V
Input Logic-High, Seal Mode (SDA, SCL, $\overline{KIN}$ , MPC)	$V_{IH\_SEAL}$	Seal mode	4.1			V
		Seal mode, $V_{CC} \geq 2.7V$	2.2			V
Input Logic-Low, Seal Mode (SDA, SCL, $\overline{KIN}$ , MPC)	$V_{IL\_SEAL}$	Seal mode			0.5	V
Output Logic-Low (SDA, $\overline{RST}$ , $\overline{KOUT}$ )	$V_{OL}$	$I_{OL} = 4mA$			0.4	V
SCL Clock Frequency	$f_{SCL}$		0		400	kHz
KIN Pullup Resistance	$R_{KIN}$			210		k $\Omega$
Bus Free Time Between a Stop and Start Condition	$t_{BUF}$		1.3			$\mu s$
Start Condition (Repeated) Hold Time	$t_{HD:STA}$	(Note 3)	0.6			$\mu s$
Low Period of SCL Clock	$t_{LOW}$		1.3			$\mu s$
High Period of SCL Clock	$t_{HIGH}$		0.6			$\mu s$
Setup Time for a Repeated Start Condition	$t_{SU:STA}$		0.6			$\mu s$
Data Hold Time	$t_{HD:DAT}$	(Note 4)	0		0.9	$\mu s$
Data Setup Time	$t_{SU:DAT}$		100			ns
Setup Time for Stop Condition	$t_{SU:STO}$		0.6			$\mu s$
Spike Pulse Widths Suppressed by Input Filter	$t_{SP}$		50			ns

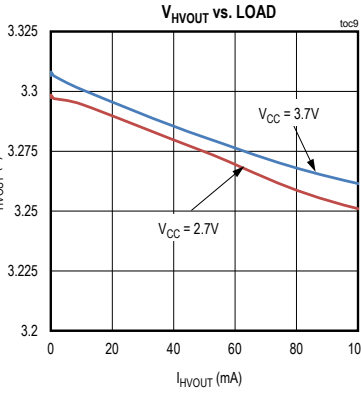
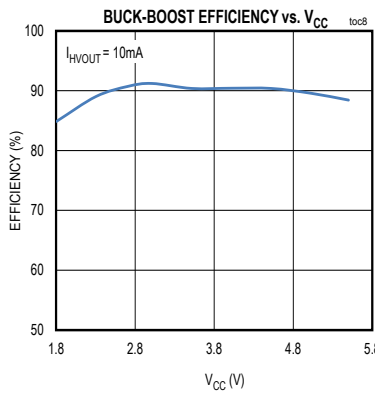
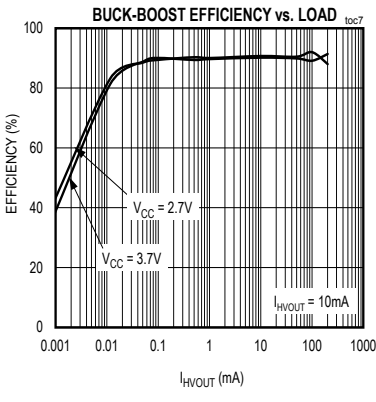
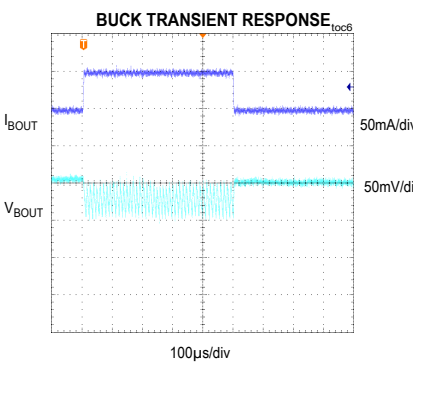
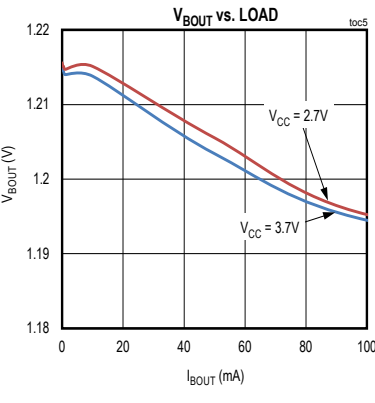
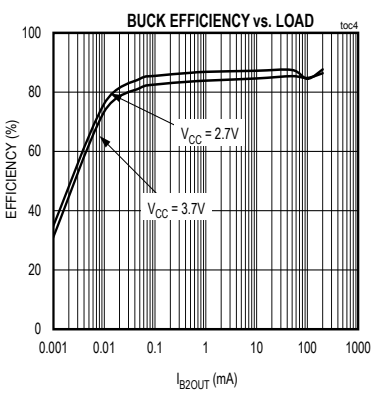
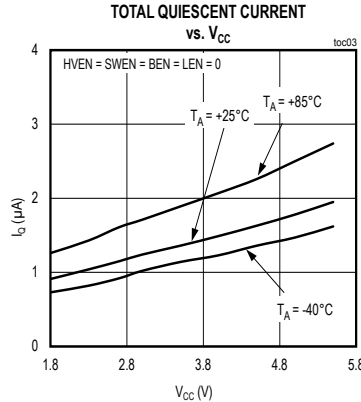
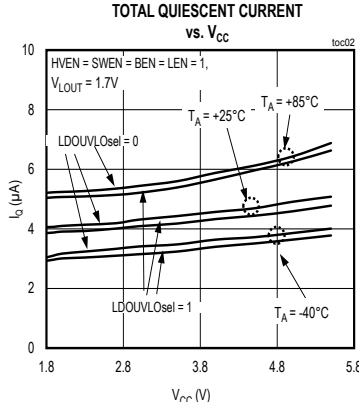
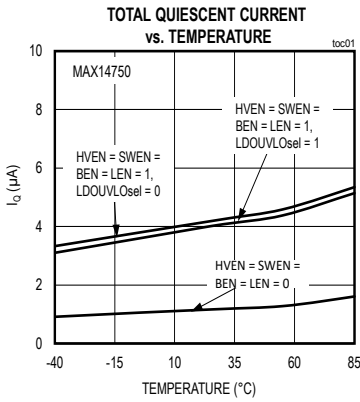
**Note 2:** All devices are 100% production tested at  $T_A = +25^{\circ}C$ . Limits over the operating temperature range are guaranteed by design.

**Note 3:**  $f_{SCL}$  must meet the minimum clock low time plus the rise/fall times.

**Note 4:** The maximum  $t_{HD:DAT}$  has to be met only if the device does not stretch the low period ( $t_{LOW}$ ) of the SCL signal.

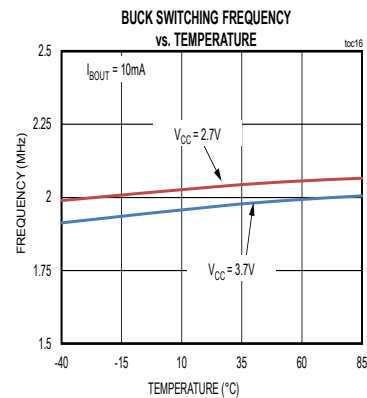
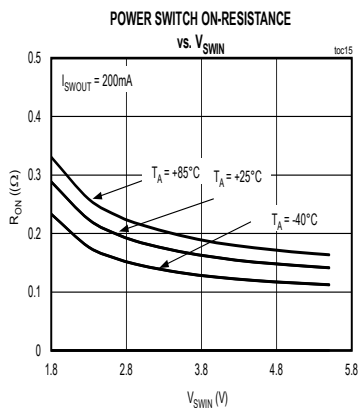
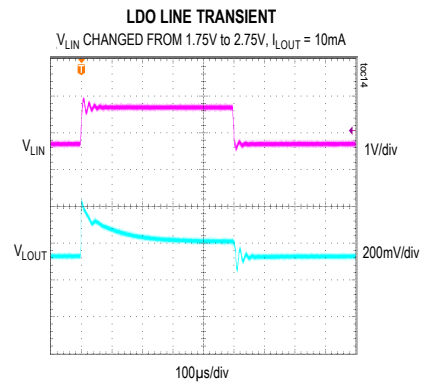
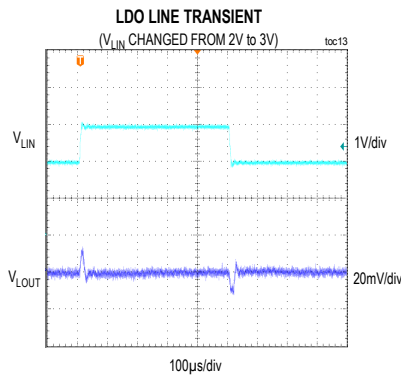
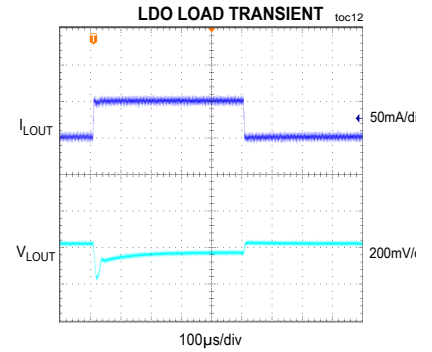
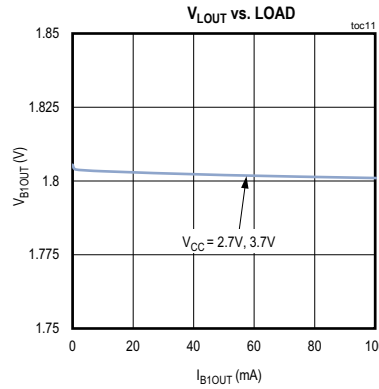
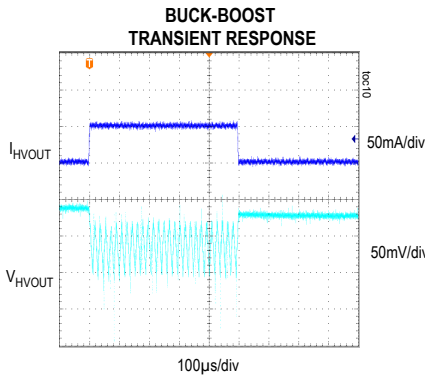
Typical Operating Characteristics

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = +25^\circ C$ , all registers in their default state, unless otherwise noted.)

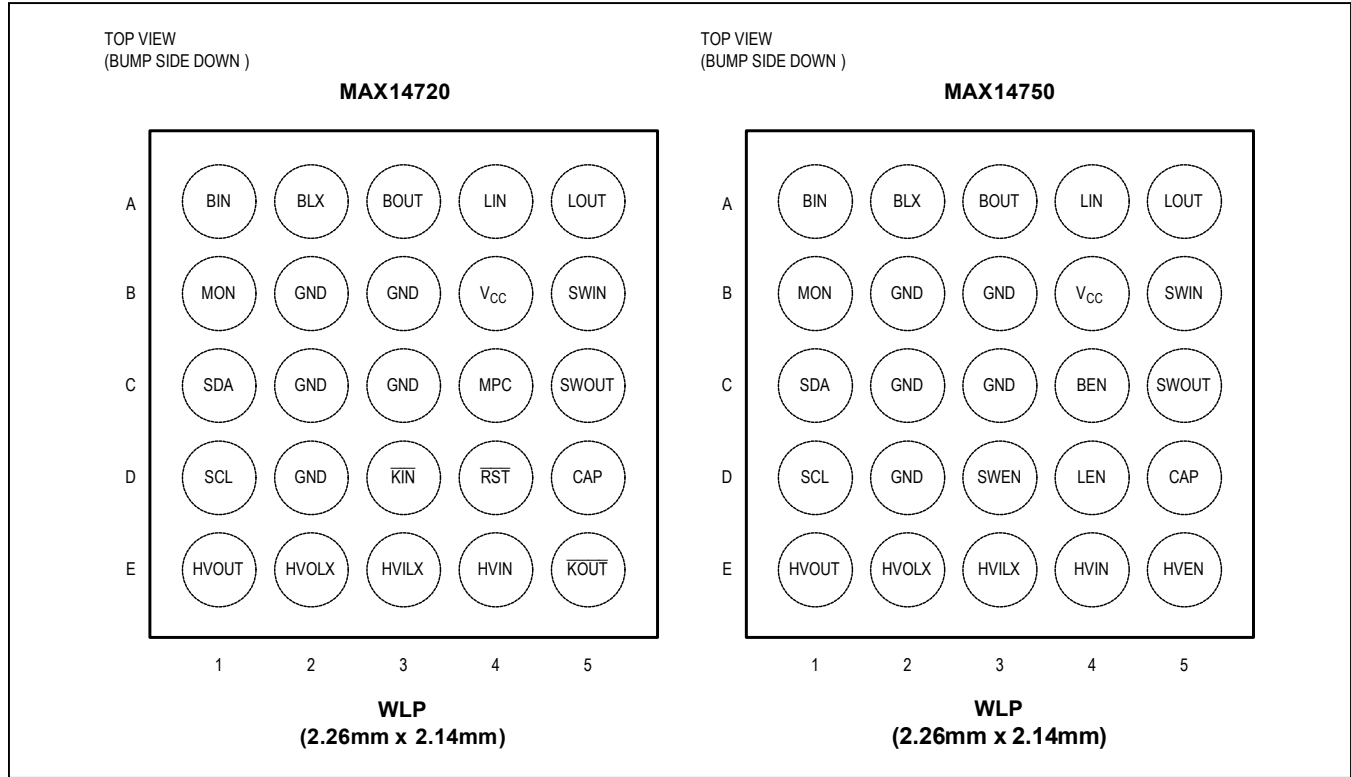


Typical Operating Characteristics (continued)

( $V_{CC} = V_{BIN} = V_{LIN} = V_{HVIN} = V_{SWIN} = 2.7V$ ,  $T_A = +25^\circ C$ , all registers in their default state, unless otherwise noted.)



### Bump Configurations



### Bump Description

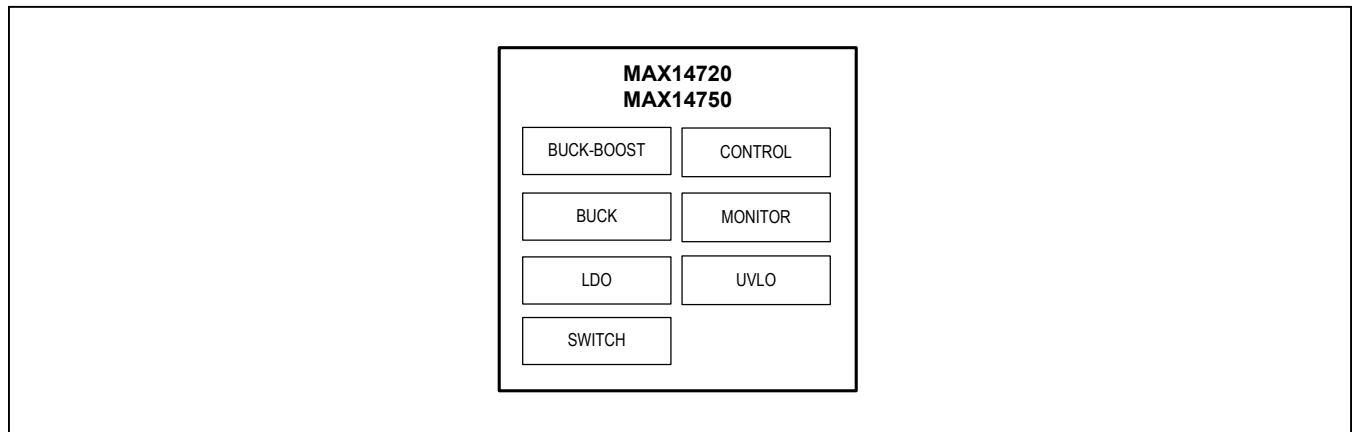
BUMP		NAME	FUNCTION
MAX14720	MAX14750		
A1	A1	BIN	Buck Regulator Input (must be connected to HVIN on the board). Bypass with a 1µF capacitor to GND.
A2	A2	BLX	Buck Regulator Switch
A3	A3	BOUT	Buck Regulator Output. Bypass with a 10µF capacitor to GND.
A4	A4	LIN	LDO Input. Bypass with a 1µF capacitor to GND.
A5	A5	LOUT	LDO Output. Bypass with a 1µF capacitor to GND.
B1	B1	MON	Monitor Multiplexer Output
B2, B3, C2, C3, D2	B2, B3, C2, C3, D2	GND	Ground
B4	B4	V <sub>CC</sub>	Power Supply Input
B5	B5	SWIN	Power Switch Input. SWIN ≤ V <sub>CC</sub>
C1	C1	SDA	Open-Drain I <sup>2</sup> C Serial Data Input/Output
C4	—	MPC	Multipurpose Control Input
—	C4	BEN	Active-High Buck Regulator Enable Input

**Bump Description (continued)**

BUMP		NAME	FUNCTION
MAX14720	MAX14750		
C5	C5	SWOUT	Power Switch Output. Bypass with a 100µF capacitor to GND for battery impedance measurement.
D1	D1	SCL	I <sup>2</sup> C Serial Clock
D3	—	$\overline{KIN}$	KEY Input. Active-low button monitor with internal 210kΩ pullup.
—	D3	SWEN	Active-High Power Switch Enable Input
D4	—	$\overline{RST}$	Active-Low, Open-Drain Reset Output
—	D4	LEN	Active-High Linear Regulator Enable Input
D5	D5	CAP	Internal Power Decoupling. Bypass with a 0.1µF capacitor to GND.
E1	E1	HVOUT	Buck-Boost Regulator Output. Bypass with a 10µF capacitor to GND.
E2	E2	HVOLX	Buck-Boost Regulator Boost Switch
E3	E3	HVILX	Buck-Boost Regulator Buck Switch
E4	E4	HVIN	Buck-Boost Regulator Input (Must be Connected to BIN on the Board). Bypass with a 1µF capacitor to GND.
E5	—	$\overline{KOUT}$	KEY Output. Active-low, open-drain buffered copy of $\overline{KIN}$ .
—	E5	HVEN	Active-High Buck-Boost Regulator Enable Input

**Note:** All capacitance values listed in this document refer to effective capacitance. Be sure to specify capacitors that will meet these requirements under typical system operating conditions taking into consideration the effects of voltage and temperature.

**Block Diagram**



## Detailed Description

### Power Regulation

The MAX14720/MAX14750 include a buck-boost regulator, a synchronous buck regulator, a low quiescent current linear regulator, and a power switch with integrated battery monitoring. Burst mode operation of the switching regulators provides excellent light-load efficiency and allows the switching regulators to run continuously without significant energy cost.

The buck-boost regulator in the devices is suitable for applications (such as low-power display biasing) that need the voltage present continuously while running from a battery. The buck-boost regulator can also operate in a current-limited mode to reduce current surges to the supply. The current-limiting is implemented by dividing down the frequency of the switching and is dependent on the ratio of the input-to-output voltage. Step-down operation is not allowed when current-limiting is active.

### UVLO

In addition to the internal power-on reset (POR) circuit, the devices also have two UVLO circuits that monitor the voltages on BIN and LIN pin to ensure that input voltages are sufficient for proper operation. It is required that the boost and buck-boost are powered from the same voltage so they share a UVLO on the BIN pin. The LDO has its own UVLO on the LIN pin. The UVLO circuits are disabled when the blocks are not enabled to reduce the quiescent current. The devices provide the ability to select which of the two UVLOs are used so that applications with BIN and LIN tied to the same supply can share a single UVLO to reduce quiescent current. The selection is made in the UVLOCfg register and the effects of the different settings are shown in the [Table 1](#). In the MAX14720, if there is a fault in a block that is enabled by the sequencer (every \_Seq[2:0] option except 000, 110 or 111) the part will transition to the shutdown and then the off state. The part will remain off until the next button press. After the button press it will wait for the fault to clear before beginning the power on sequence. A fault is any condition that causes the block to turn off when it should be enabled, such as a UVLO condition or thermal shutdown.

**Table 1. UVLO Configuration**

UVLOCfg	BBBUVLOsel	LDOUVLOsel	BIN UVLO	LIN UVLO
0x00	LIN	LIN	Disabled	Enabled
0x01	LIN	BIN	Enabled	Enabled
0x02	BIN	LIN	Enabled	Enabled
0x03	BIN	BIN	Enabled	Disabled

### Output Discharge

The regulators include circuitry to discharge their outputs. Active discharge applies a current sink, while passive discharge applies a load resistor. The active discharge is enabled during hard reset, or for 10ms as the part enters the off/seal mode. It can also be activated in the on state by a register bit when the regulator is disabled. Passive discharge is applied in the off/seal mode if the GIBPasDsc bit is set and can also be applied in the on state by a register bit when the regulator is disabled.

### Power On/Off and Reset Control

The MAX14750 provides individual enable pins for each of the primary functions, while the MAX14720 includes a push-button monitor and sequencing controller. [Figure 1](#) shows the basic flow diagram for the power-management control inside the MAX14720. Each primary function of the MAX14720 can be automatically enabled by the sequencing controller. The functions can default to be controlled by the I<sup>2</sup>C configuration registers. The default state is determined by the factory configuration. See [I<sup>2</sup>C Register Descriptions](#) section for more information.

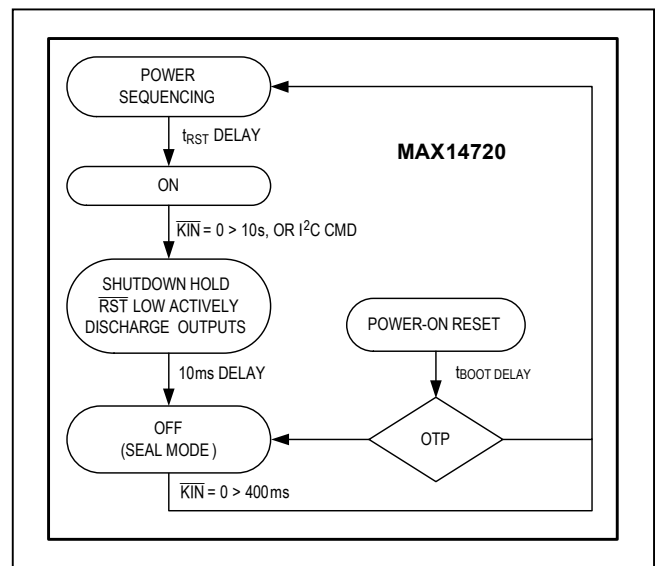


Figure 1. Power State Diagram for MAX14720

When the device begins the shutdown process, reset is driven low, all functions are disabled and outputs are actively discharged. Then, 10ms later, the device will be in the off state (seal mode) where all functions are disabled except for the power button monitor.

**Power Sequencing (MAX14720 Only)**

The sequencing of the voltage regulators during power-on is configurable. Each regulator can be configured to be turned on at one of four points during the power-on process. The four points are:  $t_{BOOT}$  after the power-on event, after the  $\overline{RST}$  signal is released, or at two points in between. The two points in between are fixed proportionally to the duration of the POR process, but the overall time of the reset delay is configurable at 80ms, 120ms, 220ms, and 420ms. (Note that the actual turn-on time of some converters may be limited by the soft-starting of the output.) [Figure 2](#) shows the timing relationship. Additionally, the regulators can be preselected to default off and can be turned on with an I<sup>2</sup>C command after reset is released.

**Battery Impedance Measurement**

The MAX14720 contains circuitry to measure the impedance of the power supply. To perform this measurement, SWIN must be connected to  $V_{CC}$ , with no capacitor present on the battery-side; all loads draw their power from the power-switch output (see [Typical Application Circuits](#)). By default, the power switch is configured with a soft-start current limit that prevents potential high current drawn from the battery. This soft-start lasts 60ms after the power switch is turned on.

During battery measurement, the impedance measurement circuitry will open the power switch and record the voltage at the input to the switch before and after a current load is

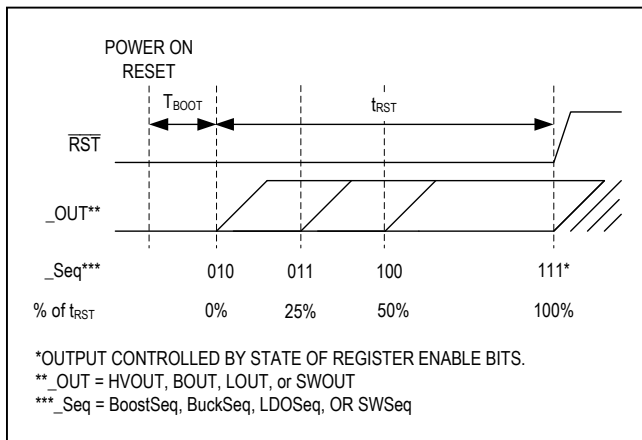


Figure 2. Reset Sequence Programming (MAX14720)

applied. During the measurement, the system must rely on the energy stored in the capacitor attached to the output of the switch for operation. If the SWOUT voltage falls below SWOUT UVLO threshold, the battery measurement is immediately aborted and the power switch closes.

The parameters of the current load and the timing of the pulse are specified in registers BatTime(0x0D) and BatCfg(0x0E) when the measurement is requested and the results are presented in registers BatV(0x0F), BatOCV(0x10), and BatLCV(0x11) (see [Figure 3](#)).

**I<sup>2</sup>C Interface**

The devices use the two-wire I<sup>2</sup>C interface to communicate with the host microcontroller. The configuration settings and status information provided through this interface are detailed in the register descriptions.

**I<sup>2</sup>C Addresses**

The registers of the devices are accessed through the slave address of 010101Ax (A is configurable by OTP).

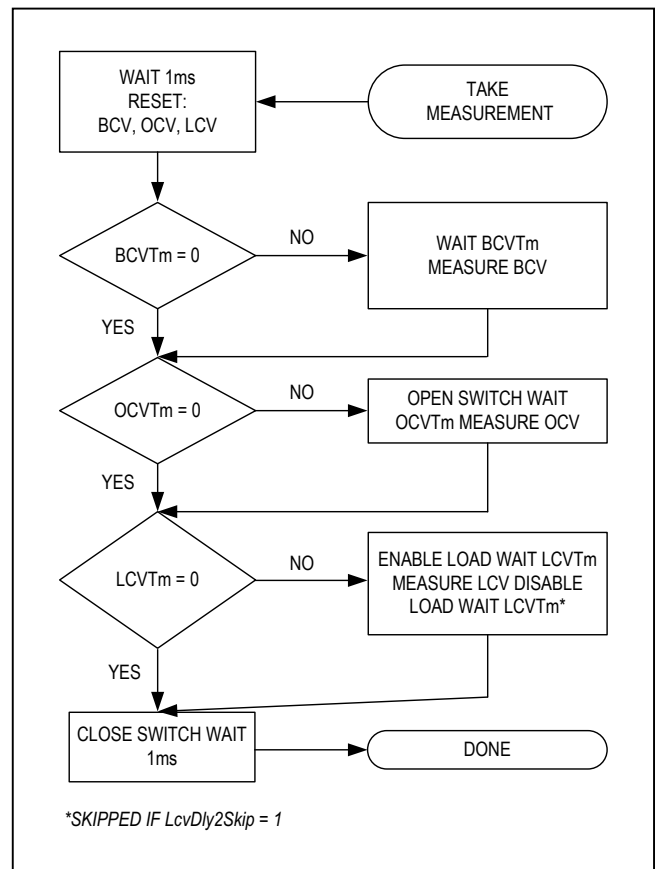


Figure 3. Battery Impedance Measurement

I<sup>2</sup>C Register Map

REGISTER ADDRESS	REGISTER NAME	B7	B6	B5	B4	B3	B2	B1	B0	
0x00	ChipId	ChipId[7:0]*								
0x01	ChipRev	ChipRev[7:0]*								
0x02	Reserved	Reserved								
0x03	BoostCDiv	<b>ClkDivSet[6:0]</b>								
0x04	BoostISet	—	—	—	—	<b>BoostISet[2:0]</b>				
0x05	BoostVSet	—	—	—	<b>BoostVSet[4:0]</b>					
0x06	BoostCfgr	<b>BoostSeq[2:0]*</b>		BoostEn[1:0]	—	BoostEMI	<b>BoostIInd</b>			
0x07	BuckVSet	<b>BuckVSet[5:0]</b>								
0x08	BuckCfgr	<b>BuckSeq[2:0]*</b>		BuckEn[1:0]	BuckMd[1:0]		<b>BuckFst</b>			
0x09	BuckISet	<b>BuckISet[2:0]</b>		<b>BuckCfgr</b>	<b>BuckIInd</b>	<b>BuckHysOff</b>	<b>BuckMinOT</b>	<b>BuckInteg</b>		
0x0A	LDOVSet	—	—	—	<b>LDOVSet[4:0]</b>					
0x0B	LDOCfgr	<b>LDOSeq[2:0]*</b>		LDO PasDSC	LDO ActDSC	LDOEn[1:0]	<b>LDOMode</b>			
0x0C	SwitchCfgr	<b>SWSeq[2:0]*</b>		—	—	SWEn[1:0]	<b>SWSofStart</b>			
0x0D	BatTime	—		<b>BCVTm[1:0]</b>	—	<b>OCVTm[1:0]</b>	<b>LCVTm[1:0]</b>			
0x0E	BatCfgr	BIA**	BIMAbort**	—	—	LcvDly2Skip	<b>BatImpCur[2:0]</b>			
0x0F	BatBCV	BCV[7:0]*								
0x10	BatOCV	OCV[7:0]*								
0x11	BatLCV	LCV[7:0]*								
0x12-0x18	Reserved	Reserved								
0x19	MONCfgr	MONEn	—	—	—	MONHiZ	MONCtr[2:0]			
0x1A	BootCfgr	<b>PwrRstCfgr[3:0]*</b>			—	<b>SftrRstCfgr*</b>	<b>PFNPUDCfgr*</b>	<b>BootDly[1:0]*</b>		
0x1B	PinStat	—	—	—	—	KIN/SWEN	KOUT/HVEN	MPC/BEN	RST/LEN	
0x1C	BBBExtra	<b>Boost HysOff</b>	<b>BoostPasDsc</b>	<b>Boost ActDsc</b>	—	—	<b>BuckPasDsc</b>	<b>BuckActDsc</b>	<b>BuckFScI</b>	
0x1D	HandShk	<b>StartOff*</b>	<b>GlbPasDsc*</b>	—	—	—	—	—	<b>StayOn</b>	
0x1E	UVLOCfgr	—	—	—	—	—	—	<b>BBBUVLOsel*</b>	<b>LDO UVLOsel</b>	
0x1F	PWROFF	PWROFFCMD[7:0]								
0x20... 0x2B	OTPMMap	Programmed Default OTP Values								

**Note:** All registers reset to default value on hard and soft reset.  
 Reserved Bits: Must not be modified from their default states to ensure proper operation.  
 Bolded Names: Bits default value can be factory configured by OTP. Bolded bits with asterisk are set by OTP only.  
 \*Read-only  
 \*\*Bits autoreset at the end of impedance measurement (either completed or aborted).



## I<sup>2</sup>C Register Descriptions

**Table 2. ChipId Register (0x00)**

<b>ADDRESS:</b>	<b>0x00 (Read-Only)</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	ChipId[7:0]							
<b>Chip_Id[7:0]</b>	Chip_Id[7:0] bits show information about the version of the MAX14720/MAX14750.							

**Table 3. ChipRev Register (0x01)**

<b>ADDRESS:</b>	<b>0x01 (Read-Only)</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	ChipRev[7:0]							
<b>ChipRev[7:0]</b>	ChipRev[7:0] bits show information about the revision of the MAX14720/MAX14750 silicon.							

**Table 4. BoostCDiv Register (0x03)**

<b>ADDRESS:</b>	<b>0x03</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	ClkDivEn	ClkDivSet[6:0]						
<b>ClkDivEn</b>	<p>Boost Current-Limited Output Mode Enable            This allows the boost regulator to be operated in a current limited output mode.            0: Normal Operation, Full Output Current Capability            1: Divided Clock Current Limited Mode            When the clock divider is enabled, the boost is operated with a fixed peak current limit and programmable frequency. The peak current is set by BoostISet[2:0] and the switching frequency is determined by ClkDivSet[6:0]. The regulator will stop switching when the voltage is above the set point and will only run when the voltage is below the output setting. This mode can only be enabled once the output voltage is set higher than the input voltage.</p>							
<b>ClkDivSet[6:0]</b>	<p>Current-Limited Boost Clock Divider Setting            When the current limited mode is enabled, the frequency of the boost regulator in current limited mode will be the frequency of the oscillator divided by the value of (10 + ClkDivSet[6:0]). The range is <math>f_{OSC}/10</math> to <math>f_{OSC}/137</math>.</p>							

**Table 5. BoostISet Register (0x04)**

<b>ADDRESS:</b>	<b>0x04</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	—	—	—	—	—	BoostISet[2:0]		
<b>BoostISet[2:0]</b>	<p>Buck-Boost Peak Current-Limit Setting            000: 0 (Minimum On-Time)            001: 50mA            010: 100mA            011: 150mA            100: 200mA            101: 250mA            110: 300mA            111: 350mA</p>							

**Table 6. BoostVSet Register (0x05)**

ADDRESS:	0x05							
BIT	7	6	5	4	3	2	1	0
NAME	—	—	—	BoostVSet[4:0]				
<b>BoostVSet[4:0]</b>	Boost Output Voltage Setting. This setting is internally latched and can change only when boost is disabled. 2.5V to 5.0V, linear scale, 100mV increments 000000 = 2.5V 000001 = 2.6V ... 011001 = 5.0V > 011001 = 5.0V							

**Table 7. BoostCfg Register (0x06)**

ADDRESS:	0x06							
BIT	7	6	5	4	3	2	1	0
NAME	BoostSeq[2:0] (Read-only)			BoostEn[1:0]		—	BoostEMI	BoostInd
<b>BoostSeq[2:0]</b>	Boost Enable Configuration (Read-Only) 000 = Disabled 001 = Reserved 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Reserved 110 = Controlled by HVEN (MAX14750) 111 = Controlled by BoostEn [1:0] after 100% of Boot/POR Process Delay Control (MAX14720)							
<b>BoostEn[1:0]</b>	Boost Enable Configuration (effective only when BoostSeq[2:0] == 111) 00 = Disabled. Active discharge behavior depends on BoostActDsc. 01 = Enabled 10 = Enabled when MPC is high 11 = Reserved							
<b>BoostEMI</b>	Boost EMI reduction. Dampens ringing of the inductor when in discontinuous mode 0 = EMI damping active (improve EMI) 1 = EMI damping disabled (improve Efficiency)							
<b>BoostInd</b>	Boost Inductance Select 1 = Inductance is 3.3μH 0 = Inductance is 4.7μH							

**Table 8. BuckVSet Register (0x07)**

ADDRESS:	0x07							
BIT	7	6	5	4	3	2	1	0
NAME	BuckVSet[5:0]							
<b>BuckVSet[5:0]</b>	Buck Output Voltage Setting This setting is internally latched and can change only when buck is disabled. 1.0V to 2.0V, linear scale, 25mV increments 000000 = 1.000V 000001 = 1.025V ... 101000 = 2.0V > 101000 = 2.0V							

**Table 9. BuckCfg Register (0x08)**

ADDRESS:	0x08							
BIT	7	6	5	4	3	2	1	0
NAME	BuckSeq[2:0] (Read-only)		BuckEn[1:0]		BuckMd[1:0]		BuckFst	
<b>BuckSeq[2:0]</b>	Buck Enable Configuration (Read-Only) 000 = Disabled 001 = Reserved 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Reserved 110 = Controlled by BEN (MAX14750) 111 = Controlled by BuckEn [1:0] after 100% of Boot/POR Process Delay Control							
<b>BuckEn[1:0]</b>	Buck Enable Configuration (effective only when BuckSeq[2:0] == 111) 00 = Disabled. Active discharge behavior depends on BuckActDsc. 01 = Enabled 10 = Enabled when MPC is high 11 = Reserved							
<b>BuckMd[1:0]</b>	Buck Mode Select 00 = Burst mode 01 = Forced PWM mode 10 = Forced PWM mode when MPC is high 11 = Reserved							
<b>BuckFst</b>	Buck Fast Start 0 = Normal startup current limit 1 = Double the startup current to reduce the startup time by half							

**Table 10. BuckISet Register (0x09)**

ADDRESS:	0x09							
BIT	7	6	5	4	3	2	1	0
NAME	BuckISet[2:0]			BuckCfg	BuckInd	BuckHysOff	BuckMinOT	BuckInteg
<b>BuckISet[2:0]</b>	Buck Peak Current Limit Setting 000: 50mA 001: 100mA 010: 150mA 011: 200mA 100: 250mA 101: 300mA 110: 350mA 111: 400mA							
<b>BuckCfg</b>	Buck Configuration 0 = set to 0 for burst mode 1 = set to 1 for FPWM mode							
<b>BuckInd</b>	Buck Inductance Select 0 = Inductance is 2.2 $\mu$ H 1 = Inductance is 4.7 $\mu$ H							
<b>BuckHysOff</b>	Buck Hysteresis Off 0 = Enable comparator hysteresis 1 = Disable comparator hysteresis (recommended to reduce voltage ripple)							
<b>BuckMinOT</b>	Buck Minimum On-Time 0 = Enable deglitch delay on comparator for better efficiency 1 = Disable deglitch delay on comparator to minimize voltage ripple							
<b>BuckInteg</b>	Buck Integrate 0 = Helps stabilize the buck regulator for high currents with small output capacitor 1 = Better load regulation at high current (recommended for output capacitance > 6 $\mu$ F)							

**Table 11. LDOVSet Register (0x0A)**

ADDRESS:	0x0A							
BIT	7	6	5	4	3	2	1	0
NAME	LDOVSet[4:0]							
<b>LDOVSet[4:0]</b>	LDO Output Voltage Setting 0.9V to 4V, linear scale, 100mV increments 00000 = 0.9V 00001 = 1.0V ... 10000 = 2.5V ... 11111 = 4.0V							

**Table 12. LDOCfg Register (0x0B)**

ADDRESS:	0x0B							
BIT	7	6	5	4	3	2	1	0
NAME	LDOSeq[2:0] (Read-Only)			LDOPasDsc	LDOActDsc	LDOEn[1:0]		LDOMode
<b>LDOSeq[2:0]</b>	LDO Enable Configuration (Read-Only) 000 = Disabled 001 = Enabled always when BAT/SYS is present 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Disabled 110 = Controlled by LEN (MAX14750) 111 = Controlled by LDOEn[1:0] after 100% of Boot/POR Process Delay Control							
<b>LDOPasDsc</b>	LDO Passive Discharge Control 0: LDO output will be discharged only entering off and hard-reset modes. 1: LDO output will be discharged only entering off and hard-reset modes and when the enable is low.							
<b>LDOActDsc</b>	LDO Active Discharge Control 0: LDO output will be actively discharged only entering off and hard-reset modes. 1: LDO output will be actively discharged only entering off and hard-reset modes and when the enable is low.							
<b>LDOEn[1:0]</b>	LDO Enable Configuration (effective only when LDOSeq[2:0] == 111) 00 = Disabled 01 = Enabled 10 = Enabled when MPC is high 11 = Reserved							
<b>LDOMode</b>	LDO Mode Control 0 = Normal LDO operating mode 1 = Load switch mode. FET is either fully on or off depending on the state of LDOEn. When FET is on, the output is unregulated and is not affected by UVLO's control block. This setting is internally latched and can change only when the LDO is disabled.							

**Table 13. SwitchCfg Register (0x0C)**

ADDRESS:	0x0C							
BIT	7	6	5	4	3	2	1	0
NAME	SWSeq[2:0] (Read-Only)			—	—	SWEn[1:0]		SWSoftStart
<b>SWSeq[2:0]</b>	SW Enable Configuration (Read-Only) 000 = Disabled 001 = Enabled always when BAT/SYS is present 010 = Enabled at 0% of Boot/POR Process Delay Control 011 = Enabled at 25% of Boot/POR Process Delay Control 100 = Enabled at 50% of Boot/POR Process Delay Control 101 = Disabled 110 = Controlled by SWEN (MAX14750) 111 = Controlled by SWEn[1:0] after 100% of Boot/POR Process Delay Control							
<b>SWEn</b>	SW Enable Configuration (effective only when SWSeq[2:0] == 111) 00 = Disabled 01 = Enabled 10 = Enabled when MPC is high 11 = Reserved							
<b>SWSoftStart</b>	SW SoftStart 0 = No soft-start is present when the switch is enabled. 1 = Current limit of 25mA (typ) is ensured for 60ms when the switch is enabled.							

**Table 14. BatTime Register (0x0D)**

ADDRESS:	0x0D							
BIT	7	6	5	4	3	2	1	0
NAME	—	—	BCVTm[1:0]		OCVTm[1:0]		LCVTm[1:0]	
<b>BCVTm[1:0]</b>	Battery Cell Voltage Timing 00: Skip battery measurement 01: Take battery measurement after 10ms delay 10: Take battery measurement after 100ms delay 11: Take battery measurement after 1000ms delay							
<b>OCVTm[1:0]</b>	Battery Open Cell Voltage Timing If this step is skipped, LCV measurement will be taken with switch closed 00: Skip OCV measurement 01: Take OCV measurement after 10ms delay 10: Take OCV measurement after 100ms delay 11: Take OCV measurement after 1000ms delay							
<b>LCVTm[1:0]</b>	Battery Loaded Cell Voltage Timing 00: Skip LCV measurement 01: Take LCV measurement after 10ms delay 10: Take LCV measurement after 100ms delay 11: Take LCV measurement after 1000ms delay							

Table 15. BatCfg Register (0x0E)

ADDRESS:	0x0E							
BIT	7	6	5	4	3	2	1	0
NAME	BIA	BIMAbort	—	—	LcvDly2Skip	BatImpCur[2:0]		
<b>BIA</b>	Battery Impedance Active Write 1 to start battery impedance measurement. If the measurement is already running, the write is ignored. Bit will remain high until the measurement is completed. 0: Battery impedance measurement is not ongoing 1: Battery impedance measurement is ongoing							
<b>BIMAbort</b>	Battery Impedance Measurement Skip Write 1 to immediately abort the battery impedance measurement 0: Battery impedance measurement is aborted 1: Battery impedance measurement is not aborted yet							
<b>LcvDly2Skip</b>	Write 1 to skip the second delay time (equal again to LCVTm) after LCV Measurement is taken. This second delay time allows V <sub>CC</sub> to recover its unloaded value before closing the power switch again. 0: Wait second delay time 1: Skip second delay time							
<b>BatImpCur [2:0]</b>	Battery Impedance Current 000: 0 001: 250μA 010: 500μA 011: 1mA 100: 2mA 101: 4mA 110: 8mA 111: Reserved							

Table 16. BatV Register (0x0F)

ADDRESS:	0x0F (Read-Only)							
BIT	7	6	5	4	3	2	1	0
NAME	BCV[7:0]							
<b>BCV[7:0]</b>	Battery Voltage Measurement Result 8-bit battery voltage measurement: $V_{CC} = [ 2.6 * (BCV[7:0]/255) + 1.1 ] V$ If BCVTm[2:0] = 00, BCV[7:0] = 0000 0000. If error occurs or the measurement is aborted, BCV[7:0] = 1111 1111.							

**Table 17. BatOCV Register (0x10)**

<b>ADDRESS:</b>	<b>0x10 (Read-Only)</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	OCV[7:0]							
<b>OCV[7:0]</b>	Battery Voltage Measurement Result 8-bit battery voltage measurement: $V_{CC} = [2.6 \times (\text{OCV}[7:0]/255) + 1.1] \text{ V}$ If OCVTm[2:0] = 00, OCV[7:0] = 0000 0000. If error occurs or the measurement is aborted, OCV[7:0] = 1111 1111.							

**Table 18. BatLCV Register (0x11)**

<b>ADDRESS:</b>	<b>0x11 (Read-Only)</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	LCV[7:0]							
<b>LCV[7:0]</b>	Battery Voltage Measurement Result 8 bit battery voltage measurement: $V_{CC} = [2.6 \times (\text{LCV}[7:0]/255) + 1.1] \text{ V}$ If LCVTm[2:0] = 00, BCV[7:0] = 0000 0000. If error occurs or the measurement is aborted, LCV[7:0] = 1111 1111.							

**Table 19. MONCfg Register (0x19)**

<b>ADDRESS:</b>	<b>0x19</b>							
<b>BIT</b>	<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
<b>NAME</b>	MonEn	—	—	—	MONtHiZ	MONCtr[2:0]		
<b>MonEn</b>	Monitor Enable 0 = Monitor function disabled 1 = Monitor function enabled							
<b>MONtHiZ</b>	MON OFF MODE Condition 0 = Pulled Low by a 100k Pulldown Resistor 1 = Hi-Z							
<b>MONCtr[2:0]</b>	MON Pin Source Selection 000 = MON connected to SWIN 001 = MON connected to SWOUT 010 = MON connected to BIN 011 = MON connected to BOUT 100 = MON connected to HVIN 101 = MON connected to HVOUT 110 = MON connected to LIN 111 = MON connected to LOUT							



**Table 20. BootCfg Register (0x1A)**

ADDRESS:	0x1A (Read-Only)							
BIT	7	6	5	4	3	2	1	0
NAME	PwrRstCfg[4:0]				SftRstCfg	PFNPUDCfg	BootDly[1:0]	
PwrRstCfg [4:0]	0000: Pin Controlled (MAX14750) 0110: Push-Button Monitor (MAX14720)							
SftRstCfg	Soft Reset Register Default 0 = Registers do not reset to default values on soft reset 1 = Registers reset to default values on soft reset							
PFNPUDCfg	$\overline{\text{KIN}}$ Pullup/Pulldown Configuration 0 = Pullups and pulldowns on control lines disabled 1 = Selective pullups and pulldowns enabled on $\overline{\text{KIN}}$ pin							
BootDly[1:0]	Boot/POR Process $t_{\text{RESET}}$ Delay Control 00 = 80ms 01 = 120ms 10 = 220ms 11 = 420ms							

**Table 21. PinStat Register (0x1B)**

ADDRESS:	0x1B (Read-Only)							
BIT	7	6	5	4	3	2	1	0
NAME (MAX14720)	—	—	—	—	$\overline{\text{KIN}}$	$\overline{\text{KOUT}}$	MPC	$\overline{\text{RST}}$
NAME (MAX14750)	—	—	—	—	SWEN	HVEN	BEN	LEN
$\overline{\text{KIN}}$ , $\overline{\text{KOUT}}$ , MPC, $\overline{\text{RST}}$ , SWEN, HVEN, BEN, LEN	Input State 0 = Pin low 1 = Pin high							

Table 22. BBBExtra Register (0x1C)

ADDRESS:	0x1C							
BIT	7	6	5	4	3	2	1	0
NAME	BoostHysOff	BoostPasDsc	BoostActDsc	—	0	BuckPasDsc	BuckActDsc	BuckFScI
<b>BoostHysOff</b>	Boost Hysteresis Off 0 = Enable comparator hysteresis 1 = Disable comparator hysteresis (recommended to reduce voltage ripple)							
<b>BoostPasDsc</b>	Boost Passive Discharge Control 0: Boost output will be discharged only when entering off and hard-reset modes. 1: Boost output will be discharged only when entering off and hard-reset modes and when BoostEn is set to 00.							
<b>BoostActDsc</b>	Boost Active Discharge Control 0: Boost output will be discharged only when entering off and hard-reset modes. 1: Boost output will be discharged only when entering off and hard-reset modes and when BoostEn is set to 00.							
<b>BuckPasDsc</b>	Buck Passive Discharge Control 0: Buck output will be discharged only when entering off and hard-reset modes. 1: Buck output will be discharged only when entering off and hard-reset modes and when BuckEn is set to 00.							
<b>BuckActDsc</b>	Buck Active Discharge Control 0: Buck output will be discharged only when entering off and hard-reset modes. 1: Buck output will be discharged only when entering off and hard-reset modes and when BuckEn is set to 00.							
<b>BuckFScI</b>	Buck Force FET scaling (it reduces $I_Q$ by lowering the nMOS power to 20% of the nominal value) 0: FET Scaling only enabled during the buck turn-on sequence 1: FET Scaling enabled during the buck turn-on sequence and also in the buck active state.							

Table 23. HandShk Register (0x1D)

ADDRESS:	0x1D (Read-Only)							
BIT	7	6	5	4	3	2	1	0
NAME	StartOff	GlbPasDsc	—	—	—	—	—	StayOn
<b>StartOff</b>	Start In Off 1: The device will start in the off mode. 0: The device begins the power-on sequence after a $V_{CC}$ power on reset.							
<b>GlbPasDsc</b>	Global Passive Discharge 0: Passive discharge loads are disabled in off mode. 1: Passive discharge loads are enabled in off mode.							
<b>StayOn</b>	Processor Handshake This bit is used to ensure that the processor booted correctly. This bit must be set within 5s of power-on to prevent the part from shutting down and returning to the power-off condition. This bit has no effect after being set. 0 = Shutdown 5s after power-on 1 = Stay on							

**Table 24. UVLOCfg Register (0x1E)**

ADDRESS:	0x1E							
BIT	7	6	5	4	3	2	1	0
NAME	—	—	—	—	—	—	BBBUVLOsel (Read Only)	LDOUVLOsel
<b>BBBUVLOsel</b>	Buck/Buck-Boost UVLO Select 0: Buck and buck-boost are turned off/on according to LIN_UVLO thresholds 1: Buck and buck-boost are turned off/on according to BIN_UVLO thresholds							
<b>LDOUVLOsel</b>	LDO UVLO Select 0: LDO is turned off/on according to LIN_UVLO thresholds 1: LDO is turned off/on according to BIN_UVLO thresholds							

**Table 25. PWRCFG Register (0x1F)**

ADDRESS:	0x1F							
BIT	7	6	5	4	3	2	1	0
NAME	PWROFFCMD[7:0]							
<b>PWROFFCMD [7:0]</b>	Power-Off Command Writing 0xB2 to this register will place the part in the off state/seal mode. Waking up the device from this mode requires a low pulse on $\overline{KIN}$ . All other codes = Do nothing							

### I<sup>2</sup>C Interface

The MAX14720/MAX14750 contain an I<sup>2</sup>C-compatible interface for data communication with a host controller (SCL and SDA). The interface supports a clock frequency of up to 400kHz. SCL and SDA require pullup resistors that are connected to a positive supply.

#### Start, Stop, And Repeated Start Conditions

When writing to the MAX14720/MAX14750 using I<sup>2</sup>C, the master sends a START condition (S) followed by the MAX14720/MAX14750 I<sup>2</sup>C address. After the address, the master sends the register address of the register that is to be programmed. The master then ends communication by issuing a STOP condition (P) to relinquish control of the bus, or a REPEATED START condition (Sr) to communicate to another I<sup>2</sup>C slave. See [Figure 4](#).

**Table 26. I<sup>2</sup>C Slave Addresses**

ADDRESS FORMAT	HEX	BINARY
7-Bit Slave ID	0x2A	0101010
Write Address	0x54	0000 0100
Read Address	0x55	01010101

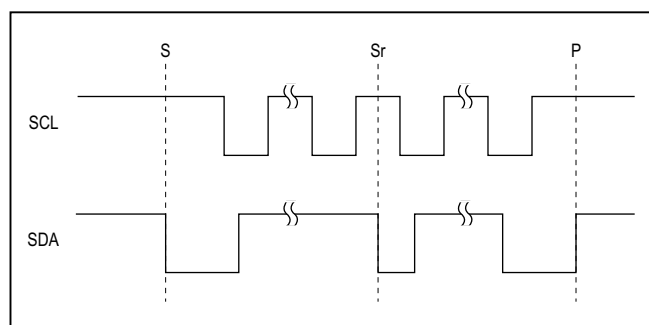


Figure 4. I<sup>2</sup>C START, STOP, and REPEATED START Conditions

#### Slave Address

Set the Read/Write bit high to configure the devices to read mode ([Table 26](#)). Set the Read/Write bit low to configure the MAX14720/MAX14750 to write mode. The address is the first byte of information sent to the MAX14720/MAX14750 after the START condition.

#### Bit Transfer

One data bit is transferred on the rising edge of each SCL clock cycle. The data on SDA must remain stable during the high period of the SCL clock pulse. Changes in SDA while SCL is high and stable are considered control signals (see the [Start, Stop, And Repeated Start Conditions](#) section). Both SDA and SCL remain high when the bus is not active.

#### Single-Byte Write

In this operation, the master sends an address and two data bytes to the slave device ([Figure 5](#)). The following procedure describes the single byte write operation:

- 1) The master sends a START condition
- 2) The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends 8 data bits
- 7) The slave asserts an ACK on the data line
- 8) The master generates a STOP condition

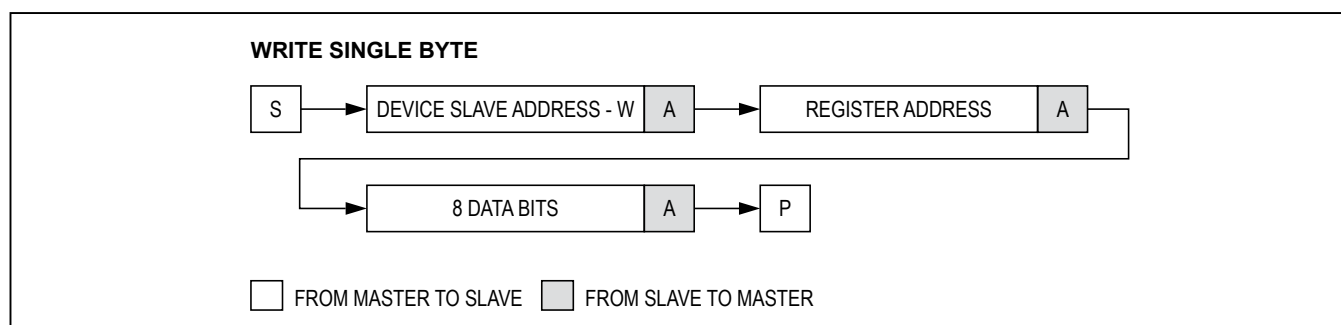


Figure 5. Write Byte Sequence

**Burst Write**

In this operation, the master sends an address and multiple data bytes to the slave device (Figure 6). The slave device automatically increments the register address after each data byte is sent, unless the register being accessed is 0x00, in which case the register address remains the same. The following procedure describes the burst write operation:

- 1) The master sends a START condition
- 2) The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends eight data bits
- 7) The slave asserts an ACK on the data line
- 8) Repeat 6 and 7 N-1 times
- 9) The master generates a STOP condition

**Single Byte Read**

In this operation, the master sends an address plus two data bytes and receives one data byte from the slave device (I2C Register Descriptions). The following procedure describes the single byte read operation:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address plus a write bit (low).
- 3) The addressed slave asserts an ACK on the data line.
- 4) The master sends the 8-bit register address.
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not).
- 6) The master sends a REPEATED START condition.
- 7) The master sends the 7-bit slave address plus a read bit (high).
- 8) The addressed slave asserts an ACK on the data line.
- 9) The slave sends eight data bits.
- 10) The master asserts a NACK on the data line.
- 11) The master generates a STOP condition.

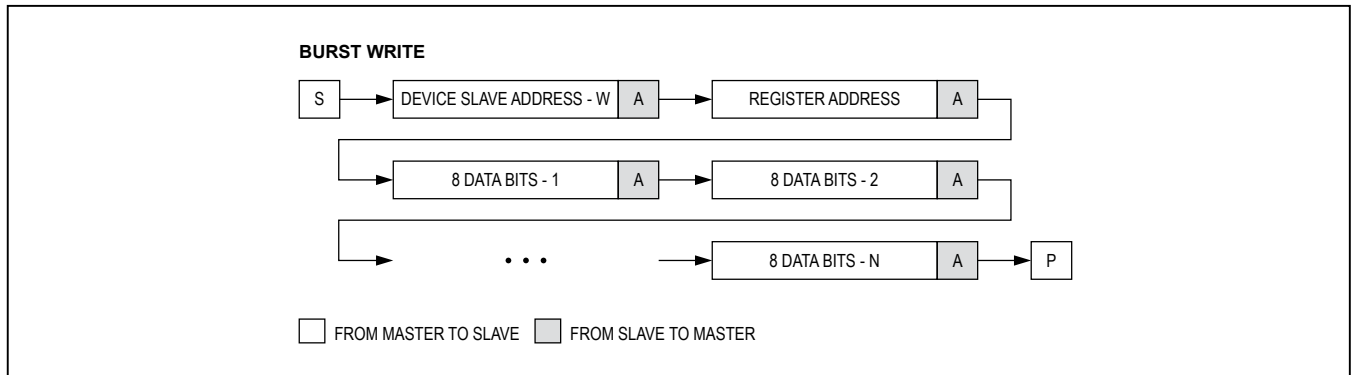


Figure 6. Burst Write Sequence

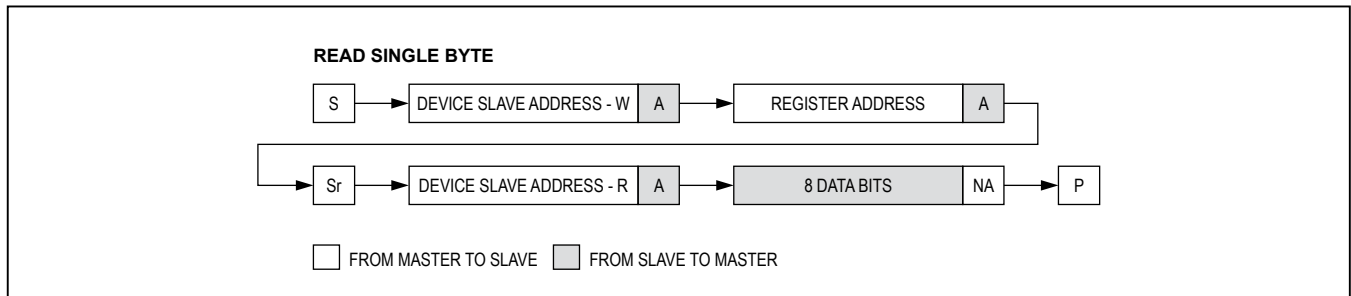


Figure 7. Read Byte Sequence

**Burst Read**

In this operation, the master sends an address plus two data bytes and receives multiple data bytes from the slave device (Figure 8). The following procedure describes the burst byte read operation:

- 1) The master sends a START condition
- 2) The master sends the 7-bit slave address plus a write bit (low)
- 3) The addressed slave asserts an ACK on the data line
- 4) The master sends the 8-bit register address
- 5) The slave asserts an ACK on the data line only if the address is valid (NAK if not)
- 6) The master sends a REPEATED START condition
- 7) The master sends the 7-bit slave address plus a read bit (high)
- 8) The slave asserts an ACK on the data line
- 9) The slave sends eight data bits
- 10) The master asserts an ACK on the data line

- 11) Repeat 9 and 10 N-2 times
- 12) The slave sends the last eight data bits
- 13) The master asserts a NACK on the data line
- 14) The master generates a STOP condition

**Acknowledge Bits**

Data transfers are acknowledged with an acknowledge bit (ACK) or a not-acknowledge bit (NACK). Both the master and the MAX14720/MAX14750 generate ACK bits. To generate an ACK, pull SDA low before the rising edge of the ninth clock pulse and hold it low during the high period of the ninth clock pulse (Figure 9). To generate a NACK, leave SDA high before the rising edge of the ninth clock pulse and leave it high for the duration of the ninth clock pulse. Monitoring for NACK bits allows for detection of unsuccessful data transfers.

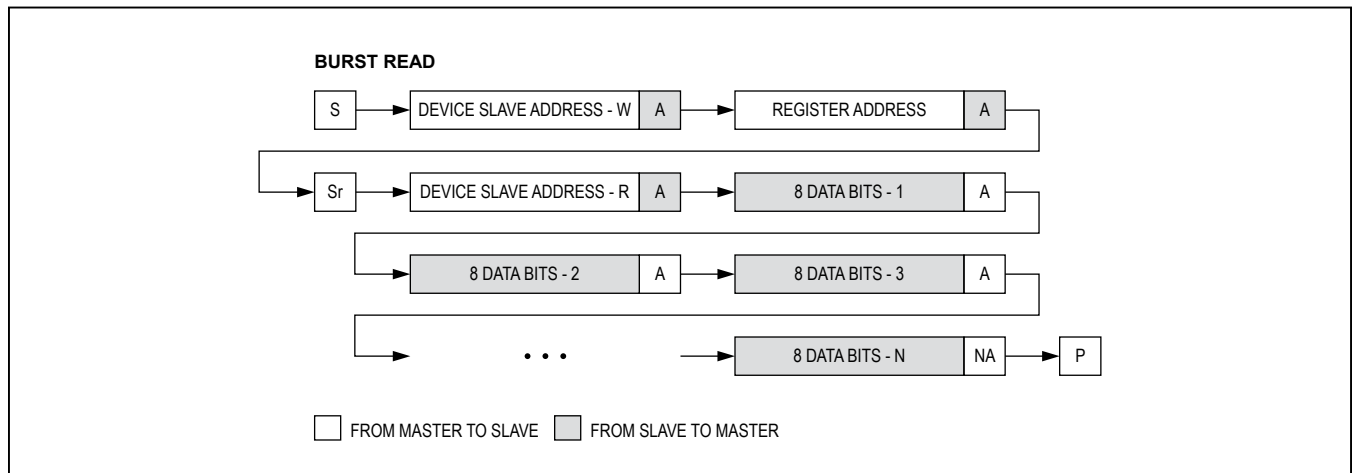


Figure 8. Burst Read Sequence

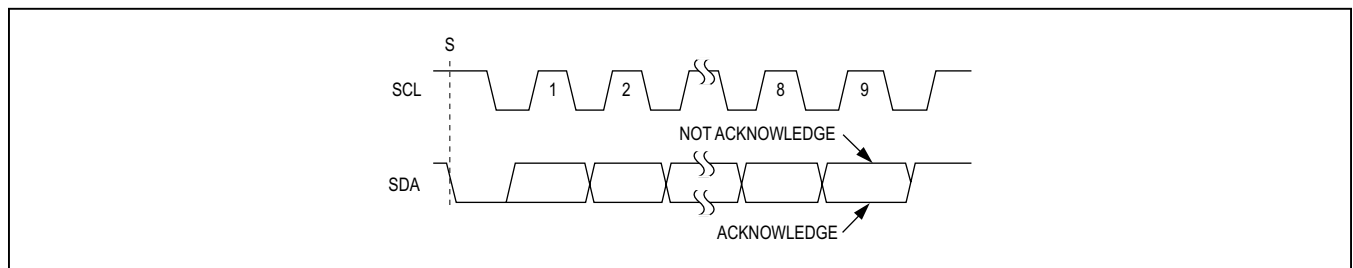


Figure 9. Acknowledge

Table 27. Register Bit Default Values

REGISTER BITS	MAX14750A	MAX14720A	MAX14720B
BoostISet[2:0]	100mA	100mA	100mA
BoostVSet[4:0]	3.3V	3.3V	3.3V
BBBUVLOSel	BIN	BIN	BIN
LDOUVLOSel	LIN	BIN	BIN
BuckVSet[5:0]	1.2V	1.2V	1.8V
BuckISet[2:0]	300mA	300mA	300mA
BuckCfg	Burst	Burst	Burst
BuckInd	2.2μH	2.2μH	2.2μH
BuckHysOff	Lower Ripple	Lower Ripple	Lower Ripple
BuckMinOT	Lower Ripple	Lower Ripple	Lower Ripple
BuckInteg	Higher DC Accuracy	Higher DC Accuracy	Higher DC Accuracy
I2CAAdd	0101010	0101010	0101011
StayOn	Stay On	Stay On	Stay On
LDOVSet[4:0]	1.8V	1.8V	1.8V
BoostSeq[2:0]	HVEN	BoostEn	BoostEn
BoostInd	4.7μH	4.7μH	4.7μH
BuckSeq[2:0]	BEN	50%	50%
BuckFst	Zero	Zero	Zero
LDOSeq[2:0]	LEN	50%	LDOEn (I <sup>2</sup> C)
LDOMode	LDO	LDO	Load Switch
SWSeq[2:0]	SWEN	0%	0%
SWSofStart	none	25mA (typ) for 60ms	25mA (typ) for 60ms
BCVTm[1:0]	Skip	Skip	Skip
OCVTm[1:0]	Skip	Skip	Skip
LCVTm[1:0]	Skip	Skip	Skip
LDOPasDSC	Off	Off	Off
LDOActDSC	Off	Off	Off
BatImpCur	0mA	0mA	0mA
PwrRstCfg[3:0]	Pin Enable	$\overline{KIN}$	$\overline{KIN}$
SftRstCfg	Hold Regs	Hold Regs	Hold Regs
PFNPUDCfg	Disabled	Enabled	Enabled
BootDly[1:0]	80ms	120ms	120ms
StartOff	Power On	Remain Off	Remain Off
GlbPasDsc	Disabled	Disabled	Disabled
BoostHysOff	More Efficient	More Efficient	More Efficient

**Table 27. Register Bit Default Values (continued)**

REGISTER BITS	MAX14750A	MAX14720A	MAX14720B
BoostPasDsc	Off	Off	Off
BoostActDsc	Off	Off	Off
BuckPasDsc	Off	Off	Off
BuckActDsc	Off	Off	Off
BuckFScI	Zero	Zero	Zero
ClkDivEna	Disabled	Disabled	Disabled
ClkDivSet[6:0]	0	0	0

**Table 28. Register Default Values**

REGISTER ADDRESS	REGISTER NAME	DEFAULT VALUES		
		MAX14750A	MAX14720A	MAX14720B
0x00	ChipId	0x01	0x01	0x01
0x01	ChipRev	0x01	0x01	0x01
0x02	Reserved	0x00	0x00	0x00
0x03	BoostCDiv	0x00	0x00	0x00
0x04	BoostISet	0x02	0x02	0x02
0x05	BoostVSet	0x08	0x08	0x08
0x06	BoostCfg	0xC0	0xE0	0xE0
0x07	BuckVSet	0x08	0x08	0x20
0x08	BuckCfg	0xC0	0x80	0x80
0x09	BuckISet	0xA7	0xA7	0xA7
0x0A	LDOVSet	0x09	0x09	0x09
0x0B	LDOCfg	0xC0	0x80	0xE1
0x0C	SwitchCfg	0xC0	0x41	0x41
0x0D	BatTime	0x00	0x00	0x00
0x0E	BatCfg	0x00	0x00	0x00
0x0F	BatBCV	0x00	0x00	0x00
0x10	BatOCV	0x00	0x00	0x00
0x11	BatLCV	0x00	0x00	0x00
0x12	Reserved	0x00	0x00	0x00
0x13	Reserved	0x00	0x00	0x00
0x14	Reserved	0x00	0x00	0x00
0x15	Reserved	0x00	0x00	0x00
0x16	Reserved	0x00	0x00	0x00
0x17	Reserved	0x00	0x00	0x00
0x18	Reserved	0x34	0x34	0x34



**Table 28. Register Default Values (continued)**

REGISTER ADDRESS	REGISTER NAME	DEFAULT VALUES		
		MAX14750A	MAX14720A	MAX14720B
0x19	MONCfg	0x00	0x00	0x00
0x1A	BootCfg	0x00	0x61	0x61
0x1B	PinStat	0x00	0x00	0x00
0x1C	BBBExtra	0x00	0x00	0x00
0x1D	HandShk	0x01	0x81	0x81
0x1E	UVLOCfg	0x02	0x03	0x03
0x1F	PWROFF	0x00	0x00	0x00

**Typical Application Circuits**

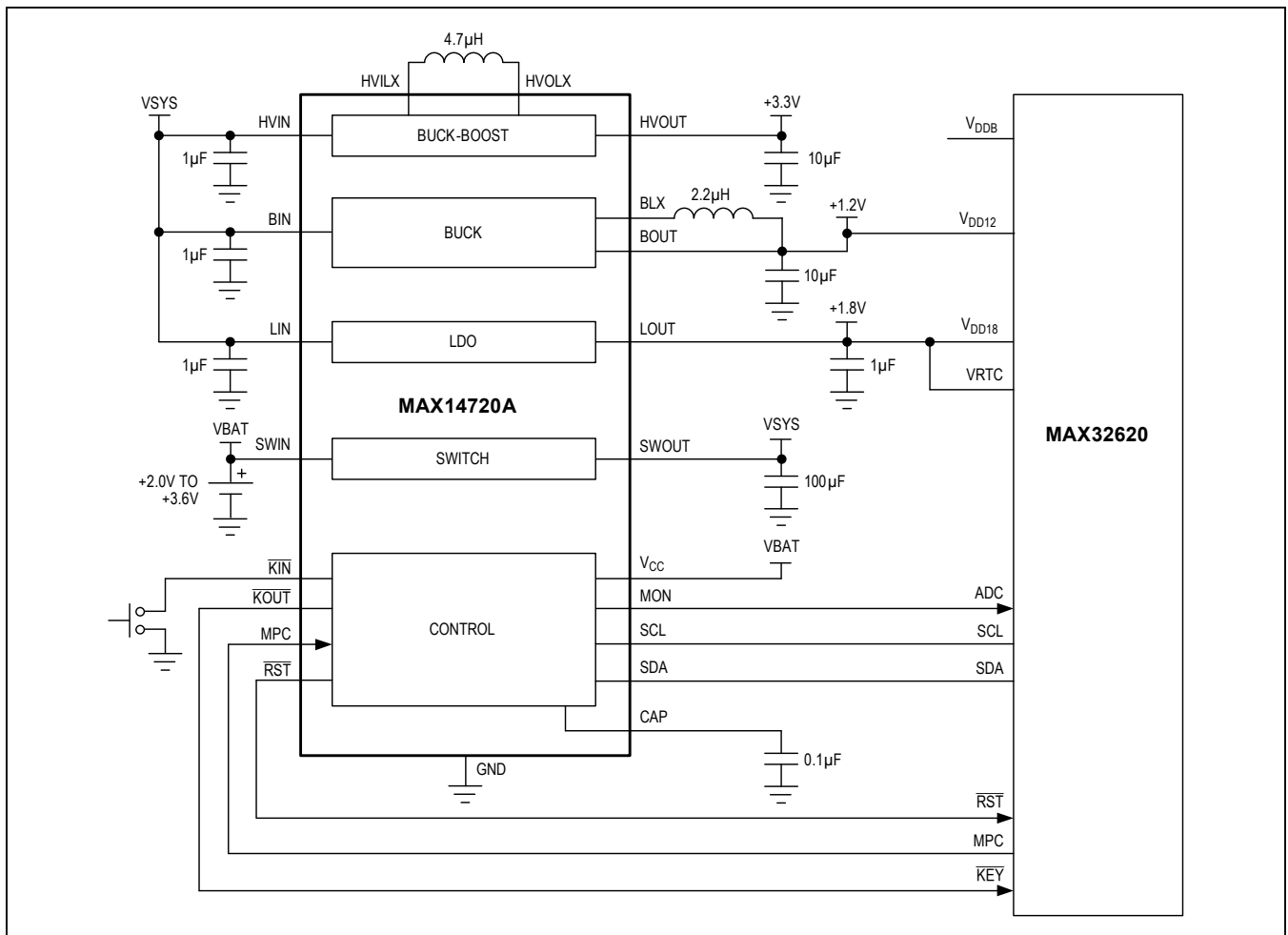


Figure 10. Lithium Coin Cell

Typical Application Circuits (continued)

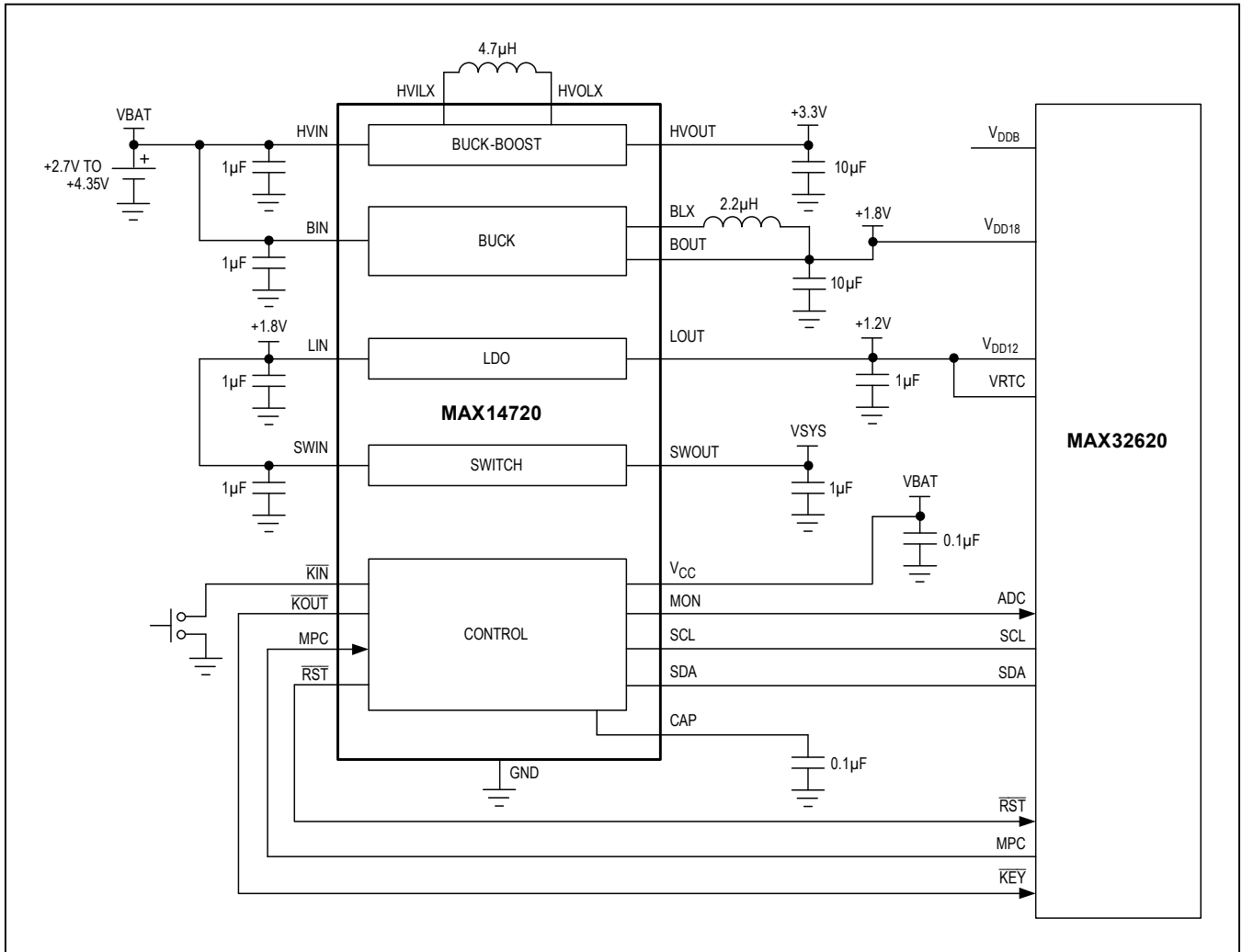


Figure 11. Removable Li+ Rechargeable

Typical Application Circuits (continued)

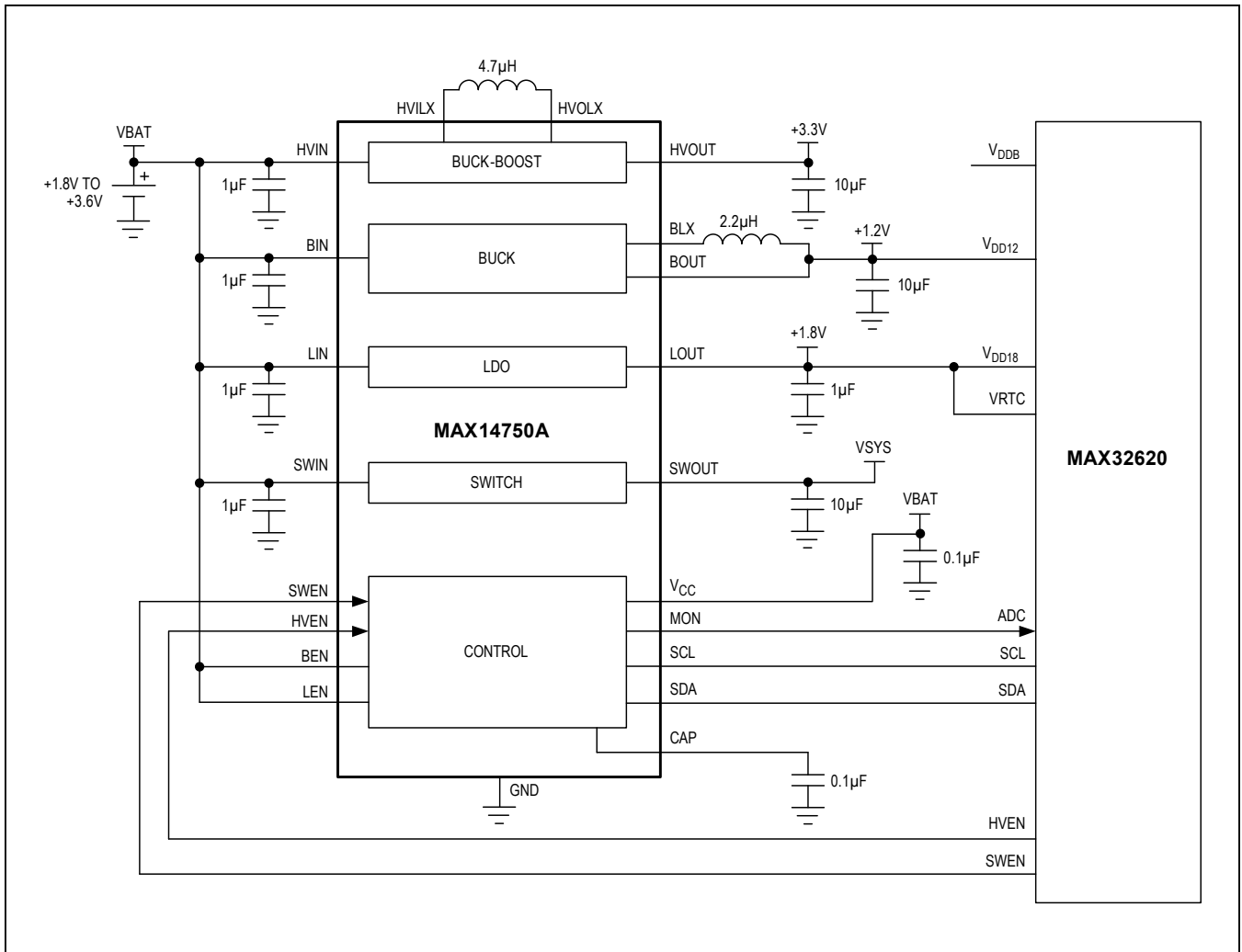


Figure 12. Always-On Coin Cell

Typical Application Circuits (continued)

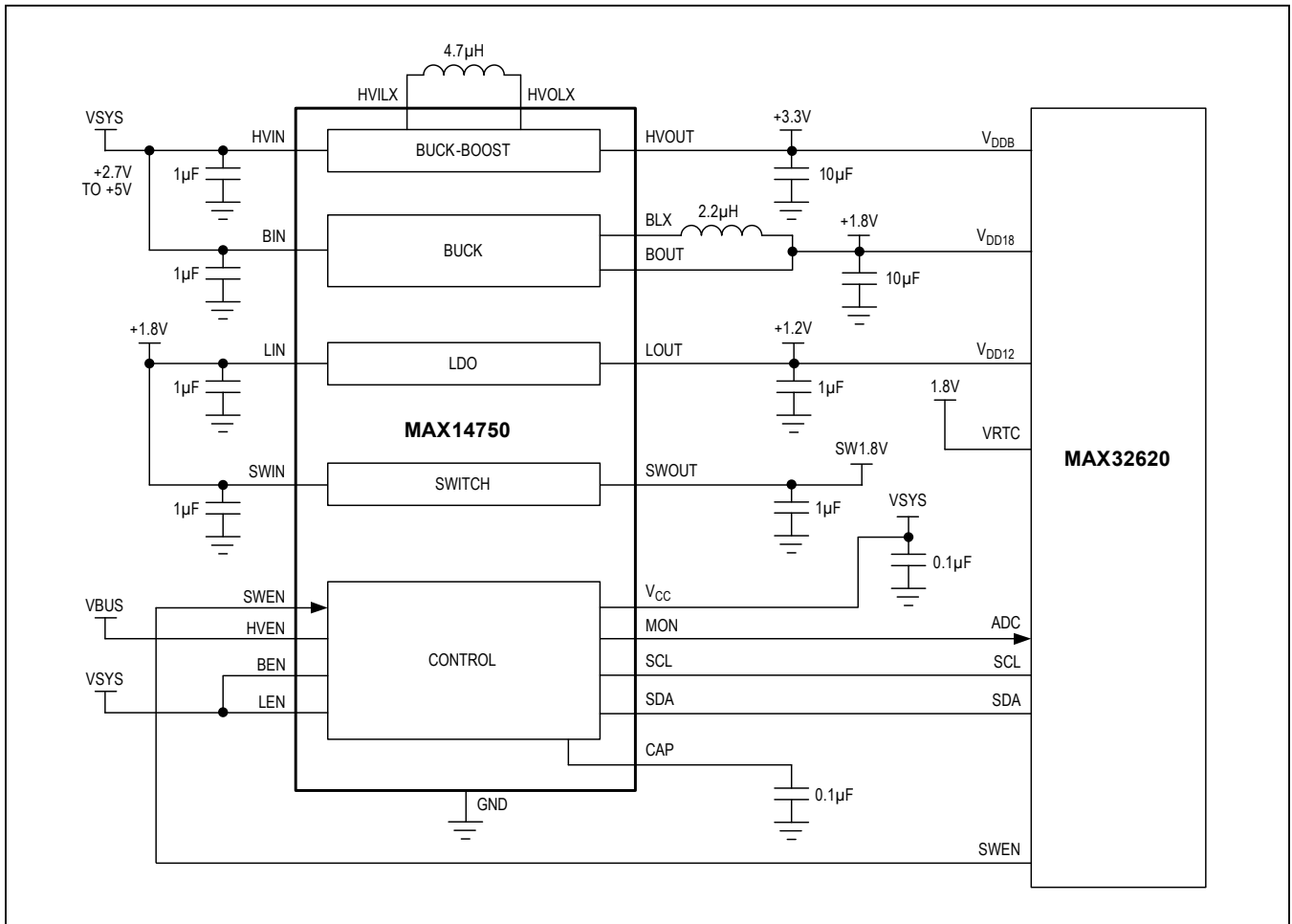


Figure 13. Companion Li+ Rechargeable

**Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
<b>MAX14720AEWA+</b>	-40°C to +85°C	25 WLP
MAX14720AEWA+T	-40°C to +85°C	25 WLP
MAX14720BEWA+*	-40°C to +85°C	25 WLP
MAX14720BEWA+T*	-40°C to +85°C	25 WLP
<b>MAX14750AEWA+</b>	-40°C to +85°C	25 WLP
MAX14750AEWA+T	-40°C to +85°C	25 WLP
MAX14750BEWA+*	-40°C to +85°C	25 WLP
MAX14750BEWA+T*	-40°C to +85°C	25 WLP

+Denotes a lead(Pb)-free/RoHS-compliant package.

\*Future product—contact factory for availability.

T = Tape and reel.

**Chip Information**

PROCESS: BiCMOS

**Package Information**

For the latest package outline information and land patterns (footprints), go to [www.maximintegrated.com/packages](http://www.maximintegrated.com/packages). Note that a “+”, “#”, or “-” in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
25 WLP	W252M2+1	<a href="#">21-0788</a>	Refer to <a href="#">Application Note 1891</a>

## Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	12/15	Initial release	—
1	2/16	<i>Worst-Case Accuracy of Single <math>V_{CC}</math> Measurement</i> spec updated in <i>Electrical Characteristics</i> table	8
2	8/16	General updates	16, 21, 31–33

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at [www.maximintegrated.com](http://www.maximintegrated.com).

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